56F8014

Data Sheet Preliminary Technical Data

·Com.cn 56F8000 16-bit Digital Signal Controllers

MC56F8014 Rev. 9 01/2007



freescale.com

Document Revision History

Version History	Description of Change					
Rev 0	Initial release					
Rev 1	Updates to Part 10, Specifications, Table 10-1, added maximum clamp current, per pin Table 10-11, clarified variation over temperature table and graph Table 10-15, added LIN slave timing					
Rev 2	Added alternate pins to Figure 11-1 and Table 11-1.					
Rev 3	Corrected bit selects in Timer Channel 3 Input (TC3_INP) bit 9, Section 6.3.1.7, clarified Section 1.4.1, and simplified notes in Table 10-9,					
Rev 4	Added clarification on sync inputs in Section 1.4.1, added voltage difference specification to Table 10-1 and Table 10-4, deleted formula for Ambient Operating Temperature in Table 10-4, and a note for pin group 3, corrected Table 8-1, error in Port C peripheral function configuration, updated notes in Table 10-9. Added RoHs and "pb-free" language to back cover.					
Rev 5	Updates to Section 10 Table 10-5, corrected max values for ADC Input Current High and Low; corrected typ value for pull-up disabled Digital Input Current Low (a) Table 10-6, corrected typ and added max values for Standby > Stop and Powerdown modes Table 10-7, corrected min value for Low-Voltage Interrupt for 3.3V Table 10-11, corrected typ and max values and units for PLL lock time Table 10-12, corrected typ values for Relaxation Oscillator output frequency and variation over temperature (also increased temp range to 150 degreesC) and added variation over temperature from 0—105 degreesC Updated Figure 10-5 Table 10-19, updated max values for Integral Non-Linearity full input signal range, Negative Differential Non-Linearity, ADC internal clock, Offset Voltage Internal Ref, Gain Error and Offset Voltage External Ref; updated typ values for Negative Differential Non-Linearity, Offset Voltage Internal Ref, Gain Error and Offset Voltage External Ref; added new min values and corrected typ values for Signal-to-noise ratio, Total Harmonic Distortion, Spurious Free Dynamic Range, Signal-to-noise plus distortion, Effective Number of Bits					
Rev 6	Added details to Section 1. Clarified language in State During Reset column in Table 2-3; corrected flash data retention temperature in Table 10-4; moved input current high/low toTable 10-19 and location of footnotes in Table 10-5; reorganized Table 10-19; clarified title of Figure 10-1.					
Rev. 7	 In Table 10-4, added an entry for flash data retention with less than 100 program/erase cycles (minimum 20 years). In Table 10-6, changed the device clock speed in STOP mode from 8MHz to 4MHz. In Table 10-12, changed the typical relaxation oscillator output frequency in Standby mode from 400kHz to 200kHz. 					
Rev. 8	In Table 10-19, changed the maximum ADC internal clock frequency from 8MHz to 5.33MHz.					

Version History	Description of Change
Rev. 9	Added the following note to the description of the TMS signal in Table 2-3: Note: Always tie the TMS pin to V_{DD} through a 2.2K resistor.

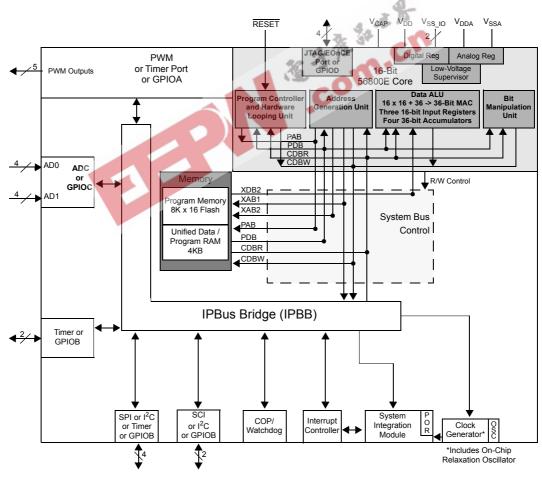
Please see http://www.freescale.com for the most current data sheet revision.



56F8014 General Description

- Up to 32 MIPS at 32MHz core frequency
- DSP and MCU functionality in a unified, C-efficient architecture
- 16KB Program Flash
- 4KB Unified Data/Program RAM
- One 5-channel PWM module
- Two 4-channel 12-bit ADCs
- One Serial Communication Interface (SCI) with LIN slave functionality
- One Serial Peripheral Interface (SPI)
- One 16-bit Quad Timer

- One Inter-Integrated Circuit (I²C) Port
- Computer Operating Properly (COP)/Watchdog
- On-Chip Relaxation Oscillator
- Integrated Power-On Reset and Low-Voltage Interrupt
 Module
- JTAG/Enhanced On-Chip Emulation (OnCE™) for unobtrusive, real-time debugging
- · Up to 26 GPIO lines
- 32-pin LQFP Package



56F8014 Block Diagram

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Part 1 Overview

1.1 56F8014 Features

1.1.1 Digital Signal Controller Core

- Efficient 16-bit 56800E family Digital Signal Controller (DSC) engine with dual Harvard architecture
- As many as 32 Million Instructions Per Second (MIPS) at 32MHz core frequency
- Single-cycle 16 × 16-bit parallel Multiplier-Accumulator (MAC)
- Four 36-bit accumulators, including extension bits
- 32-bit arithmetic and logic multi-bit shifter
- Parallel instruction set with unique DSP addressing modes
- Hardware DO and REP loops
- Three internal address buses
- Four internal data buses
- Instruction set supports both DSP and controller functions
- Controller-style addressing modes and instructions for compact code
- Efficient C compiler and local variable support
- Software subroutine and interrupt stack with depth limited only by memory
- JTAG/Enhanced On-Chip Emulation (OnCE) for unobtrusive, processor speed-independent, real-time debugging

1.1.2 Memory

- Dual Harvard architecture permits as many as three simultaneous accesses to program and data memory
- Flash security and protection that prevent unauthorized users from gaining access to the internal Flash
- On-chip memory
 - 16KB of Program Flash
 - 4KB of Unified Data/Program RAM
- EEPROM emulation capability using Flash

1.1.3 Peripheral Circuits for 56F8014

- One multi-function five-output Pulse Width Modulator (PWM) module
 - Up to 96MHz PWM operating clock
 - 15 bits of resolution
 - Center-aligned and Edge-aligned PWM signal mode
 - Three programmable fault inputs with programmable digital filter
 - Double-buffered PWM registers

- Taking into account values setting ADC high- and low-limit registers, each complementary PWM signal pair allows selection of a PWM supply source from:
 - PWM generator
 - External GPIO
 - Internal timers
 - ADC conversion result
- Two independent 12-bit Analog-to-Digital Converters (ADCs)
 - 2 x 4 channel inputs
 - Supports both simultaneous and sequential conversions
 - ADC conversions can be synchronized by both PWM and timer modules
 - Sampling rate up to 2.67MSPS
 - 8-word result buffer registers
 - ADC Smart Power Management (Auto-standby, auto-powerdown)
- One 16-bit multi-purpose Quad Timer module (TMR)
 - Up to 96MHz operating clock
 - Four independent 16-bit counter/timers with cascading capability
 - Each timer has capture and compare capability
 - Up to 12 operating modes
- One 16-bit multi-purpose Quad Timer module (TMR)
 - Up to 96MHz operating clock
 - Four independent 16-bit counter/timers with cascading capability
 - Each timer has capture and compare capability
 - Up to 12 operating modes
- One 16-bit multi-purpose Quad Timer module (TMR)
 - Up to 96MHz operating clock
 - Four independent 16-bit counter/timers with cascading capability
 - Each timer has capture and compare capability
 - Up to 12 operating modes
- Computer Operating Properly (COP)/Watchdog timer capable of selecting different clock sources
- Up to 26 General-Purpose I/O (GPIO) pins with 5V tolerance
- Integrated Power-On Reset and Low-Voltage Interrupt Module
- Phase Lock Loop (PLL) provides a high-speed clock to the core and peripherals
- Clock Sources:
 - On-chip relaxation oscillator
 - External clock source
- On-chip regulators for digital and analog circuitry to lower cost and reduce noise
- JTAG/EOnCE debug programming interface for real-time debugging

1.1.4 Energy Information

- Fabricated in high-density CMOS with 5V-tolerant, TTL-compatible digital inputs
- On-chip regulators for digital and analog circuitry to lower cost and reduce noise
- Wait and Stop modes available
- ADC smart power management
- Each peripheral can be individually disabled to save power

1.2 56F8014 Description

The 56F8014 is a member of the 56800E core-based family of Digital Signal Controllers (DSCs). It combines, on a single chip, the processing power of a DSP and the functionality of a microcontroller with a flexible set of peripherals to create an extremely cost-effective solution. Because of its low cost, configuration flexibility, and compact program code, the 56F8014 is well-suited for many applications. The 56F8014 includes many peripherals that are especially useful for industrial control, motion control, home appliances, general purpose inverters, smart sensors, fire and security systems, power management, and medical monitoring applications.

The 56800E core is based on a Harvard-style architecture consisting of three execution units operating in parallel, allowing as many as six operations per instruction cycle. The MCU-style programming model and optimized instruction set allow straightforward generation of efficient, compact DSP and control code. The instruction set is also highly efficient for C compilers to enable rapid development of optimized control applications.

The 56F8014 supports program execution from internal memories. Two data operands can be accessed from the on-chip data RAM per instruction cycle. The 56F8014 also offers up to 26 General Purpose Input/Output (GPIO) lines, depending on peripheral configuration.

The 56F8014 Digital Signal Controller includes 16KB of Program Flash and 4KB of Unified Data/Program RAM. Program Flash memory can be independently bulk erased or erased in pages. Program Flash page erase size is 512 Bytes/256 Words.

A key application-specific feature of the 56F8014 is the inclusion of one Pulse Width Modulator (PWM) module. This module incorporates three complementary, individually programmable PWM signal output pairs and is also capable of supporting five independent PWM functions to enhance motor control functionality. Complementary operation permits programmable dead time insertion, and separate top and bottom output polarity control. The up-counter value is programmable to support a continuously variable PWM frequency. Edge-aligned and center-aligned synchronous pulse width control (0% to 100% modulation) is supported. The device is capable of controlling most motor types: ACIM (AC Induction Motors), both BDC and BLDC (Brush and Brushless DC motors), SRM and VRM (Switched and Variable Reluctance Motors), and stepper motors. The PWM incorporates fault protection and cycle-by-cycle current limiting with sufficient output drive capability to directly drive standard optoisolators. A "smoke-inhibit", write-once protection feature for key parameters is also included. A patented PWM waveform distortion correction circuit is also provided. Each PWM is double-buffered and includes interrupt controls to permit integral reload rates to be programmable from 1/2 (center-aligned mode only) to 16. The PWM module provides reference outputs to synchronize the Analog-to-Digital Converter (ADC) through Quad Timer, Channels 2 and 3.

This Digital Signal Controller also provides a full set of standard programmable peripherals that include one Serial Communications Interface (SCI), one Serial Peripheral Interface (SPI), one Quad Timer, and one Inter-Integrated Circuit (I²C) interface. Any of these interfaces can also be used as General Purpose Input/Outputs (GPIOs).

1.3 Award-Winning Development Environment

Processor ExpertTM (PE) provides a Rapid Application Design (RAD) tool that combines easy-to-use component-based software application creation with an expert knowledge system.

The CodeWarrior Integrated Development Environment is a sophisticated tool for code navigation, compiling, and debugging. A complete set of evaluation modules (EVMs), demonstration board kit and development system cards will support concurrent engineering. Together, PE, CodeWarrior and EVMs create a complete, scalable tools solution for easy, fast, and efficient development.

1.4 Architecture Block Diagram

The 56F8014's architecture is shown in Figure 1-1, Figure 1-2, and Figure 1-3. Figure 1-1 illustrates how the 56800E system buses communicate with internal memories and the IPBus Bridge. Figure 1-2 and Figure 1-3 show the peripherals and control blocks connected to the IPBus Bridge. The figures do not show the on-board regulator and power and ground signals. They also do not show the multiplexing between peripherals or the dedicated GPIOs. Please see Part 2 Signal/Connection Descriptions to see which signals are multiplexed with those of other peripherals.

1.4.1 PWM, TMR and ADC Connections

Figure 1-3 shows the over/under voltage connections from the ADC to the PWM and the connections to the PWM from the TMR and GPIO. These signals can control the PWM outputs in a similar manner to the over/under voltage control signals. See the **56F801X Peripheral Reference Manual** for additional information.

The PWM_reload_sync output can be connected to the TMR channel 3 input and the TMR channels 2 and 3 outputs are connected to the ADC sync inputs. TMR channel 3 output is connected to SYNC0 and TMR channel 2 is connected to SYNC1. SYNC0 is the master ADC sync input that is used to trigger ADCA and ADCB in sequence and parallel mode. SYNC1 is used to trigger ABCB in parallel independent mode. These are controlled by bits in the SIM Control Register; see Section 6.3.1.

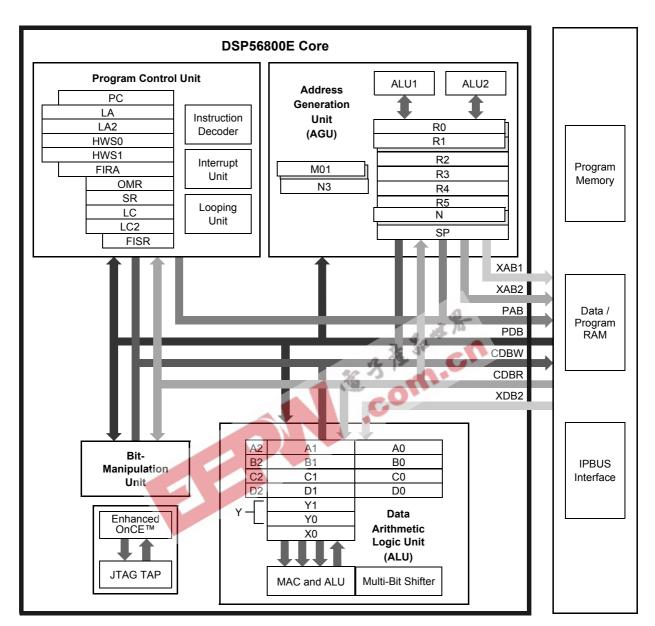
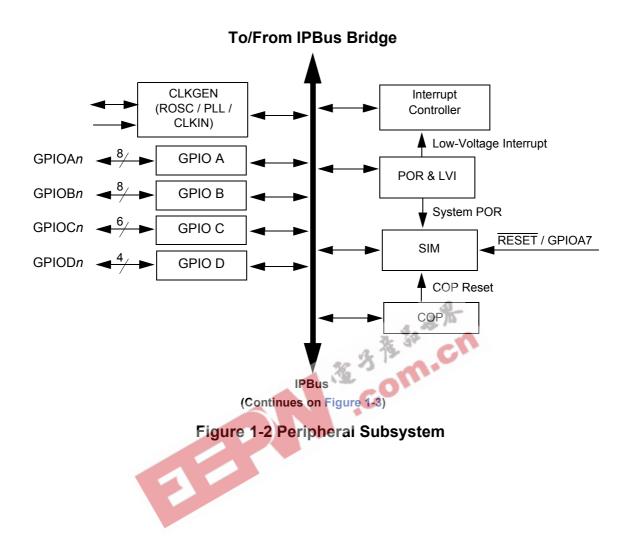
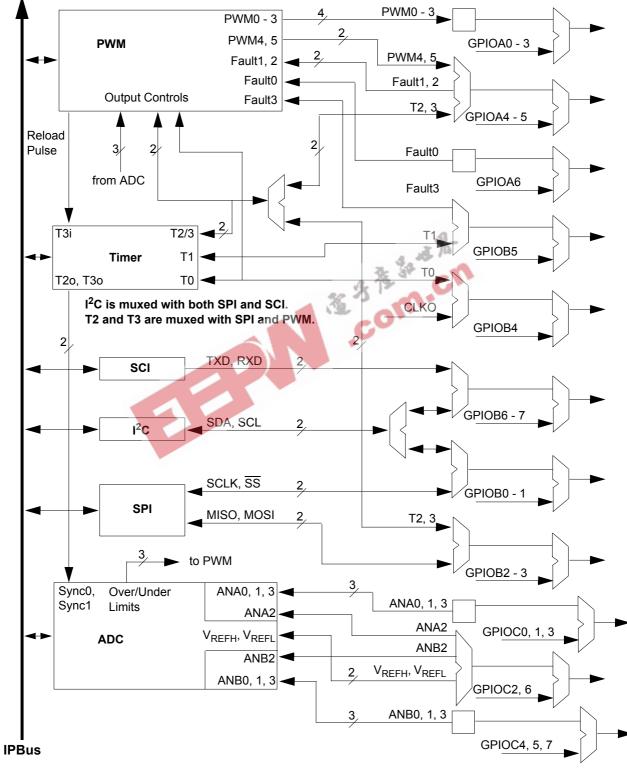


Figure 1-1 56800E Core Block Diagram

Architecture Block Diagram



(Continued from Figure 1-2) To/From IPBus Bridge





56F8014 Technical Data, Rev. 9

1.5 Product Documentation

The documents listed in **Table 1-1** are required for a complete description and proper design with the 56F8014. Documentation is available from local Freescale distributors, Freescale Semiconductor sales offices, Freescale Literature Distribution Centers, or online at:

http://www.freescale.com

Торіс	Description	Order Number
DSP56800E Reference Manual	Detailed description of the 56800E family architecture, 16-bit Digital Signal Controller core processor, and the instruction set	DSP56800ERM
56F801X Peripheral Reference Manual	Detailed description of peripherals of the 56F801X family of devices	MC56F8000RM
56F801x Serial Bootloader User Guide	Detailed description of the Serial Bootloader in the 56F801x family of devices	56F801xBLUG
56F8014 Technical Data Sheet	Electrical and timing specifications, pin descriptions, and package descriptions (this document)	MC56F8014
56F8014 Errata	Details any chip issues that might be present	MC56F8014E

Table 1-1 56F8014 Chip Documentation

1.6 Data Sheet Conventions

This data sheet uses the following conventions:

OVERBARThis is used to indicate a signal that is active when pulled low. For example, the RESET pin is
active when low.

"asserted" A high true (active high) signal is high or a low true (active low) signal is low.

"deasserted" A high true (active high) signal is low or a low true (active low) signal is high.

Examples:	Signal/Symbol	Logic State	Signal State	Voltage ¹
	PIN	True	Asserted	V _{IL} /V _{OL}
	PIN	False	Deasserted	V _{IH} /V _{OH}
	PIN	True	Asserted	V _{IH} /V _{OH}
	PIN	False	Deasserted	V _{IL} /V _{OL}

1. Values for V_{IL} , V_{OL} , V_{IH} , and V_{OH} are defined by individual product specifications.

Part 2 Signal/Connection Descriptions

2.1 Introduction

The input and output signals of the 56F8014 are organized into functional groups, as detailed in **Table 2-1**. **Table 2-2** summarizes all device pins. In **Table 2-2**, each table row describes the signal or signals present on a pin, sorted by pin number.

Functional Group	Number of Pins
Power (V _{DD} or V _{DDA})	2
Ground (V _{SS} or V _{SSA})	3
Supply Capacitors	- 1- 1
Reset	
Pulse Width Modulator (PWM) Ports ¹	5
Serial Peripheral Interface (SPI) Ports ²	4
Analog-to-Digital Converter (ADC) Ports	8
Timer Module Ports ³	2
Serial Communications Interface (SCI) Ports ⁴	2
JTAG/Enhanced On-Chip Emulation (EOnCE)	4

Table 2-1 Functional Group Pin Allocations

1. Pins in this section can function as TMR and GPIO.

2. Pins in this section can function as TMR, I^2C , and GPIO.

3. Pins can function as PWM and GPIO.

4. Pins in this section can function as $\mathsf{I}^2\mathsf{C}$ and GPIO.

Introduction

			Perip	nerals	:							
LQFP Pin #	Pin Name	Signal Name	GPIO	I2C	SCI	SPI	ADC	PWM	Quad Timer	Power & Ground	JTAG	Misc.
1	GPIOB1	GPIOB1, SS , SDA	B1	SDA		SS						
2	GPIOB7	GPIOB7, TXD, SCL	B7	SCL	TXD							
3	GPIOB5	GPIOB5, T1, FAULT3	B5					FAULT3	T1			
4	ANB0	ANB0, GPIOC4	C4				ANB0					
5	ANB1	ANB1, GPIOC5	C5				ANB1					
6	ANB2	ANB2, V _{REFL} , GPIOC6	C6				ANB2, V _{REFL}	4				
7	ANB3	ANB3, GPIOC7	C7				ANB3	4.167	5			
8	VDDA	V _{DDA}					1 3	34	1	V _{DDA}		
9	VSSA	V _{SSA}				3	ST	A.		V _{SSA}		
10	ANA3	ANA3, GPIOC3	C3				ANA3					
11	ANA2	ANA2, V _{REFH} , GPIOC2	C2)		ANA2, V _{REFH}					
12	ANA1	ANA1, GPIOC1	C1				ANA1					
13	ANA0	ANA0, GPIOCO	C0				ANA0					
14	VSS_IO	V _{SS_IO}								V _{SS_IO}		
15	тск	TCK, GPIOD2	D2								тск	
16	RESET	RESET, GPIOA7	A7									RESET
17	GPIOB3	GPIOB3, MOSI, T3	B3			MOSI			Т3			
18	GPIOB2	GPIOB2, MISO, T2	B2			MISO			T2			
19	GPIOB4	GPIOB4, T0, CLKO	B4						Т0			CLKO
20	GPIOA5	GPIOA5, PWM5, FAULT2, T3	A5					PWM5, FAULT2	Т3			
21	GPIOB0	GPIOB0, SCLK, SCL	B0	SCL		SCLK						
22	GPIOA4	GPIOA4, PWM4, FAULT1, T2	A4					PWM4, FAULT1	T2			
23	GPIOA2	GPIOA2, PWM2	A2					PWM2				
24	VCAP	V _{CAP}								V _{CAP}		

Table 2-2 56F8014 Pins

Peripherals:												
LQFP Pin #	Pin Name	Signal Name	GPIO	I2C	SCI	SPI	ADC	PWM	Quad Timer	Power & Ground	JTAG	Misc.
25	VDD_IO	V _{DD_IO}								V _{DD_IO}		
26	VSS_IO	V _{SS_IO}								V _{SS_IO}		
27	GPIOA1	GPIOA1, PWM1	A1					PWM1				
28	GPIOA0	GPIOA0, PWM0	A0					PWM0				
29	TDI	TDI, GPIOD0	D0								TDI	
30	TMS	TMS, GPIOD3	D3								TMS	
31	TDO	TDO, GPIOD1	D1								TDO	
32	GPIOB6	GPIOB6, RXD, SDA, CLKIN	B6	SDA								CLKIN
SDA, CLKIN												

Table 2-2 56F8014 Pins (Continued)

Introduction

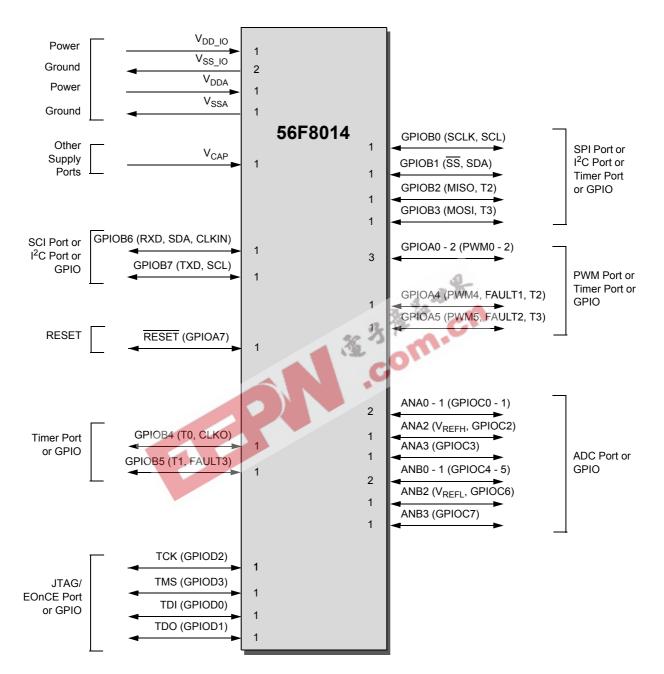


Figure 2-1 56F8014 Signals Identified by Functional Group (32-Pin LQFP)

2.2 56F8014 Signal Pins

After reset, each pin is configured for its primary function (listed first). Any alternate functionality must be programmed.

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
V _{DD_IO}	25	Supply	Supply	I/O Power — This pin supplies 3.3V power to the chip I/O interface.
V _{SS_IO}	14	Supply	Supply	${f V}_{SS}$ — These pins provide ground for chip logic and I/O drivers.
V _{SS_IO}	26			e.
V _{DDA}	8	Supply	Supply	ADC Power — This pin supplies 3.3V power to the ADC modules. It must be connected to a clean analog power supply.
V _{SSA}	9	Supply	Supply	ADC Analog Ground — This pin supplies an analog ground to the ADC modules.
V _{CAP}	24	Supply	Supply	V_{CAP} — Connect this pin to a 4.4µF or greater bypass capacitor in order to bypass the core voltage regulator, required for proper chip operation. See Section 10.2.1.
GPIOB6	32	Input/ Output	Output disabled, internal pull-up	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(RXD)		Input	enabled, pin is in input	Receive Data — SCI receive data input.
(SDA ¹)		Input/ Output	mode	Serial Data — This pin serves as the I ² C serial data line.
(CLKIN)		Input		Clock Input — This pin serves as an optional external clock input.
				After reset, the default state is GPIOB6. The peripheral functionality is controlled via the SIM (See Section 6.3.8) and the CLKMODE bit of the OCCS Oscillator Control Register.
1. This signal	is also bro	ought out on	the GPIOB1 pin	l

Table 2-3 56F8014 Signal and Package Information for the 32-Pin LQFP

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
GPIOB7	2	Input/ Output	Output disabled, internal	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(TXD)		Input/ Output	pull-up enabled, pin is in input mode	Transmit Data — SCI transmit data output or transmit / receive in single wire opeation.
(SCL ²)		Input/ Output		Serial Clock — This pin serves as the I ² C serial clock.
				After reset, the default state is GPIOB7. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
2. This signal	is also br	ought out on	the GPIOB0 pin	
RESET (GPIOA7)	16	Input Input/Open Drain Output	Output disabled, internal pull-up enabled, pin is in input mode	 Reset — This input is a direct hardware reset on the processor. When RESET is asserted low, the chip is initialized and placed in the reset state. A Schmitt trigger input is used for noise immunity. The internal reset signal will be deasserted synchronous with the internal clocks after a fixed number of internal clocks. Port A GPIO — This GPIO pin can be individually programmed as an input or open drain output pin. Note that RESET functionality is disabled in this mode and the chip can only be reset via POR, COP reset, or software reset. After reset, the default state is RESET.
GPIOB4	19	Input/	Output	Port B GPIO — This GPIO pin can be individually programmed as
	13	Output	disabled, internal pull-up	an input or output pin.
(T0)		Input/ Output	enabled, pin is in input mode	T0 — Timer, Channel 0
(CLKO)		Output	moue	Clock Output — This is a buffered clock signal. Using the SIM_CLKO Select Register (SIM_CLKOSR), this pin can be programmed as any of the following: disabled (logic 0), CLK_MSTR (system clock), IPBus clock, or oscillator output. See Section 6.3.7. After reset, the default state is GPIOB4. The peripheral functionality is controlled via the SIM_Sec.
				After reset, the default state is GPIOB4. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
GPIOB5	3	Input/ Output	Output disabled, internal	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(T1)		Input/ Output	pull-up enabled, pin is in input mode	T1 — Timer, Channel 1
(FAULT3)		Output		FAULT3 — This fault input pin is used for disabling selected PWM outputs in cases where fault conditions originate off-chip.
				After reset, the default state is GPIOB5. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
тск	15	Input	Output disabled, internal pull-up	Test Clock Input — This input pin provides a gated clock to synchronize the test logic and shift serial data to the JTAG/EOnCE port. The pin is connected internally to a pull-up resistor. A Schmitt trigger input is used for noise immunity.
(GPIOD2)		Input/ Output	enabled, pin is in input mode	Port D GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is TCK.
TMS	30	Input	Output disabled, internal pull-up	Test Mode Select Input — This input pin is used to sequence the JTAG TAP controller's state machine. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor.
(GPIOD3)		Input/ Output	enabled, pin is in input mode	Port D GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is TMS.
				Note: Always tie the TMS pin to V _{DD} through a 2.2K resistor.
TDI	29	Input	Output disabled, internal pull-up	Test Data Input — This input pin provides a serial input data stream to the JTAG/EOnCE port. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor.
(GPIOD0)		Input/ Output	enabled, pin is in input mode	Port D GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is TDI.

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
TDO (GPIOD1)	31	Output Input/ Output	Output disabled, internal pull-up enabled	 Test Data Output — This tri-stateable output pin provides a serial output data stream from the JTAG/EOnCE port. It is driven in the shift-IR and shift-DR controller states, and changes on the falling edge of TCK. Port D GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is TDO.
GPIOB0	21	Input/ Output	Output disabled, internal	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(SCLK)		Input/ Output	pull-up enabled, pin is in input mode	SPI Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. A Schmitt trigger input is used for noise immunity.
(SCL ³)		Input/ Output		Serial Data — This pin serves as the I ² C serial clock. After reset, the default state is GPIOB0. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
3. This signal	is also bro	ought out on	the GPIOB7 pin	
GPIOB1	1	Input/ Output	Output disabled, internal pull-up	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(<mark>SS</mark>)		Input	enabled, pin is in input mode	SPI Slave Select — \overline{SS} is used in slave mode to indicate to the SPI module that the current transfer is to be received.
(SDA ⁴)		Input/ Output		Serial Clock — This pin serves as the I ² C serial data line.
				After reset, the default state is GPIOB1. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
4. This signal	is also bro	ought out on	the GPIOB6 pin	

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
GPIOB2	18	Input/ Output	Output disabled, internal	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(MISO)		Input/ Output	pull-up enabled, pin is in input mode	SPI Master In/Slave Out — This serial data pin is an input to a master device and an output from a slave device. The MISO line of a slave device is placed in the high-impedance state if the slave device is not selected. The slave device places data on the MISO line a half-cycle before the clock edge the master device uses to latch the data.
(T2 ⁵)		Input/ Output		T2 — Timer, Channel 2 After reset, the default state is GPIOB2. The peripheral functionality
				is controlled via the SIM. See Section 6.3.8.
5. This signal i	s also bro	ought out on	the GPIOA4 pin	The second second
GPIOB3	17	Input/ Output	Output disabled, internal	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.
(MOSI)		Input/ Output	pull-up enabled, pin is in input mode SPI Master Out/Slave In— This serial data pin is an output from a master device and an input to a slave device. The master device places data on the MOSI line a half-cycle before the clock edge the slave device uses to latch the data.	
(T3 ⁶)		Input/		T3 — Timer, Channel 3
		Output		After reset, the default state is GPIOB3. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
6. This signal i	s also bro	ought out on	the GPIOA5 pin	·
GPIOA0	28	Input/ Output	Output disabled, internal	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM0)		Output	pull-up enabled, pin is in input mode	PWM0 — This is one of the six PWM output pins. After reset, the default state is GPIOA0.

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
GPIOA1	27	Input/ Output	Output disabled, internal	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM1)		Output	pull-up enabled, pin is in input mode	PWM1 — This is one of the six PWM output pins. After reset, the default state is GPIOA1.
GPIOA2	23	Input/ Output	Output disabled, internal	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM2)		Output	pull-up enabled, pin is in input mode	PWM2 — This is one of the six PWM output pins. After reset, the default state is GPIOA2.
GPIOA4	22	Input/ Output	Output disabled, internal	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM4)		Output	pull-up enabled, pin is in input	PWM4 — This is one of the six PWM output pins.
(FAULT1)		Input	mode	Fault1 — This fault input pin is used for disabling selected PWM outputs in cases where fault conditions originate off-chip.
(T2 ⁷)		Input/ Output		T2 — Timer, Channel 2 After reset, the default state is GPIOA4. The peripheral functionality is controlled via the SIM. See Section 6.3.8.
7. This signal	is also bro	ought out on	the GPIOB2 pin	
GPIOA5	20	Input/ Output	Output disabled, internal	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM5)		Output	pull-up enabled, pin is in input	PWM5 — This is one of the six PWM output pins.
(FAULT2)		Input/ Output	mode	 Fault2 — This fault input pin is used for disabling selected PWM outputs in cases where fault conditions originate off-chip. T3 — Timer, Channel 3
(T3 ⁸)		Input/ Output		After reset, the default state is GPIOA5. The peripheral functionality is controlled via the SIM. See Section 6.3.8 .
8. This signal	is also bro	ought out on	the GPIOB3 pin	

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Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description	
ANA0	13	Input	Analog Input	ANA0 — Analog input to ADC A, channel 0	
(GPIOC0)		Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.	
				After reset, the default state is ANA0.	
ANA1	12	Input	Analog Input	ANA1 — Analog input to ADC A, channel 1	
(GPIOC1)		Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.	
				After reset, the default state is ANA1.	
ANA2	11	Input	Analog Input	ANA2 — Analog input to ADC A, channel 2	
(V _{REFH})		Input		V _{REFH} — Analog reference voltage high	
(GPIOC2)		Input/ Output		Port C GPIO \rightarrow This GPIO pin can be individually programmed as an input or output pin.	
				After reset, the default state is ANA2.	
ANA3	10	Input	Analog	ANA3 — Analog input to ADC A, channel 3	
(GPIOC3)		Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.	
				After reset, the default state is ANA3.	
ANB0	4	Input	Analog Input	ANB0 — Analog input to ADC B, channel 0	
(GPIOC4)		Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.	
				After reset, the default state is ANB0.	

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
ANB1	5	Input	Analog Input	ANB1 — Analog input to ADC B, channel 1
(GPIOC5)		Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is ANB1.
ANB2	6	Input	Analog Input	ANB2 — Analog input to ADC B, channel 2
(V _{REFL})		Input		$\mathbf{V}_{\mathbf{REFL}}$ — Analog reference voltage low. This should normally be connected to a low-noise V_{SS} .
(GPIOC6)		Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is ANB2.
ANB3	7	Input	Analog	ANB3 — Analog input to ADC B, channel 3
(GPIOC7)		Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is ANB3.
Return to Ta	ble 2-2	-		·

Part 3 OCCS

3.1 Overview

This module provides the 2X system clock frequency to the System Integration Module (SIM), which uses it to generate the various chip clocks. This module also produces the OSC_CLK signals plus the ADC clock and high-speed peripheral clock.

The on-chip clock synthesis module allows product design using an internal relaxation oscillator to run 56F801X family parts at user-selectable frequencies up to 32MHz.

3.2 Features

The On-Chip Clock Synthesis (OCCS) module interfaces to the oscillator and PLL. The OCCS module features:

- Internal relaxation oscillator
- Ability to power down the internal relaxation oscillator
- Ability to put the internal relaxation oscillator into a standby mode
- 3-bit postscaler provides control for the PLL output
- Ability to power down the internal PLL
- Provides 2X master clock frequency and OSC_CLK signals
- Provides 3X fast peripheral clock to PWM and Timer
- Safety shutdown feature is available in the event that the PLL reference clock disappears
- Can be driven from an external clock source

The clock generation module provides the programming interface for both the PLL and internal relaxation oscillator.

3.3 Operating Modes

In 56F801X family parts, either an internal oscillator or an external frequency source can be used to provide a reference clock (SYS_CLK2) to the SIM.

The 2X system clock source output from the OCCS can be described by one of the following equations:

2X system frequency = oscillator frequency

2X system frequency = (oscillator frequency X 8) / (postscaler)

where:

postscaler = 1, 2, 4, 8, 16, or 32 PLL output divider

The SIM is responsible for further dividing these frequencies by two, which will insure a 50% duty cycle in the system clock output.

The 56F801X family parts' on-chip clock synthesis module has the following registers:

- Control Register (OCCS_CR)
- Divide-by Register (OCCS_DB)
- Status Register (OCCS_SR)
- Shutdown Register (OCCS_SHUTDN)
- Oscillator Control Register (OCCS_OCTRL)

For more information on these registers, please refer to the 56F801X Peripheral Reference Manual.

3.3.1 External Clock Source

The recommended method of connecting an external clock is illustrated in Figure 3-1. The external clock source is connected to GPIOB6 / RXD.



3.4 Block Diagram

Figure 3-2 provides a block diagram which shows how the 56F8014 creates its internal clock, using the relaxation oscillator as an 8MHz clock reference for the PLL.

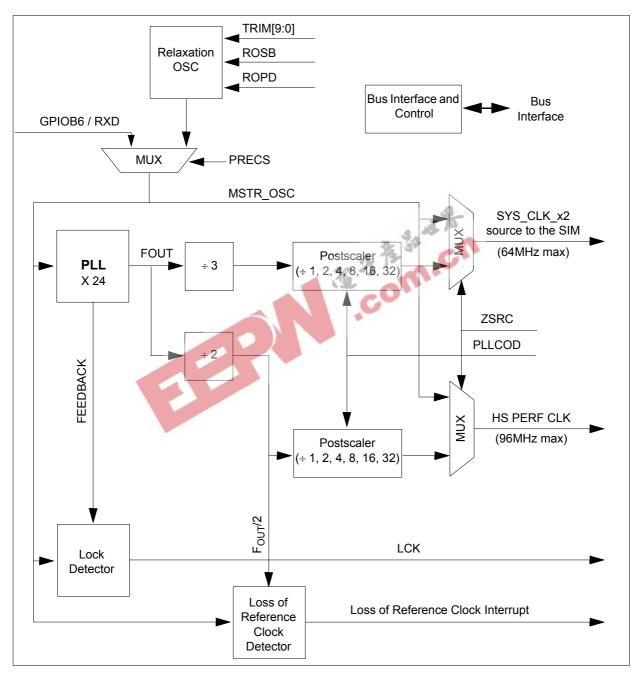


Figure 3-2 OCCS Block Diagram with Relaxation Oscillator

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3.5 Pin Descriptions

3.5.1 External Reference (GPIOB6 / RXD)

The relaxation oscillator is included on chip and the reset mode is to use this as the clock source for the chip. The user then has the option of switching to an external clock reference if desired.

Part 4 Memory Map

4.1 Introduction

The 56F8014 device is a 16-bit motor-control chip based on the 56800E core. It uses a Harvard-style architecture with two independent memory spaces for Data and Program. On-chip RAM is used in both spaces and Flash memory is used only in Program space.

This section provides memory maps for:

- Program Address Space, including the Interrupt Vector Table
- Data Address Space, including the EOnCE Memory and Peripheral Memory Maps

On-chip memory sizes for the device are summarized in Table 4-1. Flash memories' restrictions are identified in the "Use Restrictions" column of Table 4-1.

On-Chip Memory	56F8014	Use Restrictions
Program Flash (PFLASH)	8k x 16	Erase / Program via Flash interface unit and word writes to CDBW
Unified RAM (ram)	2k x 16	Usable by both the Program and Data memory spaces

Table 4-1 Chip Memory Configurations

4.2 Interrupt Vector Table

Table 4-2 provides the 56F8014's reset and interrupt priority structure, including on-chip peripherals. The table is organized with higher-priority vectors at the top and lower-priority interrupts lower in the table. As indicated, the priority of an interrupt can be assigned to different levels, allowing some control over interrupt priorities. All level 3 interrupts will be serviced before level 2, and so on. For a selected priority level, the lowest vector number has the highest priority.

The location of the vector table is determined by the Vector Base Address (VBA). Please see Section **5.6.11** for the reset value of the VBA.

By default, VBA = 0, and the reset address and COP reset address will correspond to vector 0 and 1 of the interrupt vector table. In these instances, the first two locations in the vector table must contain branch or JMP instructions. All other entries must contain JSR instructions.

Peripheral	Vector Number	Priority Level	Vector Base Address +	Interrupt Function
core			P:\$00	Reserved for Reset Overlay ²
core			P:\$02	Reserved for COP Reset Overlay
core	2	3	P:\$04	Illegal Instruction
core	3	3	P:\$06	SW Interrupt 3
core	4	3	P:\$08	HW Stack Overflow
core	5	3	P:\$0A	Misaligned Long Word Access
core	6	1-3	P:\$0C	EOnCE Step Counter
core	7	1-3	P:\$0E	EOnCE Breakpoint Unit 0
core	8	1-3	P:\$10	EOnCE Trace Buffer
core	9	1-3	P:\$12	EOnCE Transmit Register Empty
core	10	1-3	P:\$14	EOnCE Receive Register Full
core	11	2	P:\$16	SW Interrupt 2
core	12	1	P:\$18	SW Interrupt 1
core	13	0	P:\$1A	SW Interrupt 0
	14			Reserved
	15			Reserved
PS	16	0-2	P:\$20	Power Sense
OCCS	17	0-2	P:\$22	PLL Lock, Loss of Clock Reference Interrupt
FM	18	0-2	P:\$24	FM Access Error Interrupt
FM	19	0-2	P:\$26	FM Command Complete
FM	20	0-2	P:\$28	FM Command, data and address Buffers Empty
	21			Reserved
GPIOD	22	0-2	P:\$2C	GPIOD
GPIOC	23	0-2	P:\$2E	GPIOC
GPIOB	24	0-2	P:\$30	GPIOB
GPIOA	25	0-2	P:\$32	GPIOA
SPI	26	0-2	P:\$34	SPI Receiver Full / Error
SPI	27	0-2	P:\$36	SPI Transmitter Empty
SCI	28	0-2	P:\$38	SCI Transmitter Empty
SCI	29	0-2	P:\$3A	SCI Transmitter Idle
SCI	30	0-2	P:\$3C	SCI Reserved
SCI	31	0-2	P:\$3E	SCI Receiver Error
SCI	32	0-2	P:\$40	SCI Receiver Full
	33, 34			Reserved
I ² C	35	0-2	P:\$46	l ² C
Timer	36	0-2	P:\$48	Timer Channel 0
Timer	37	0-2	P:\$4A	Timer Channel 1
	1	L	(Conti	inues next page)

Table 4-2 Interrupt Vector Table Contents¹

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Peripheral	Vector Number	Priority Level	Vector Base Address +	Interrupt Function
Timer	38	0-2	P:\$4C	Timer Channel 2
Timer	39	0-2	P:\$4E	Timer Channel 3
ADC	40	0-2	P:\$50	ADCA Conversion Complete
ADC	41	0-2	P:\$52	ADCB Conversion Complete
ADC	42	0-2	P:\$54	ADC Zero Crossing or Limit Error
PWM	43	0-2	P:\$56	Reload PWM
PWM	44	0-2	P:\$58	PWM Fault
SWILP	45	-1	P:\$5A	SW Interrupt Low Priority

 Table 4-2 Interrupt Vector Table Contents¹ (Continued)

1. Two words are allocated for each entry in the vector table. This does not allow the full address range to be referenced from the vector table, providing only 19 bits of address.

2. If the VBA is set to \$0000, the first two locations of the vector table will overlay the chip reset addresses.

4.3 Program Map

The Program Memory map is shown in Table 4-3.

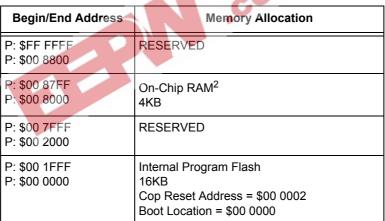


Table 4-3 Program Memory Map¹

1. All addresses are 16-bit Word addresses.

 This RAM is shared with Data space starting at address X: \$00 0000; see Figure 4-1.

4.4 Data Map

Begin/End Address	Memory Allocation
X:\$FF FFFF X:\$FF FF00	EOnCE 256 locations allocated
X:\$FF FEFF X:\$01 0000	RESERVED
X:\$00 FFFF X:\$00 F000	On-Chip Peripherals 4096 locations allocated
X:\$00 EFFF X:\$00 8800	RESERVED
X:\$00 EFFF X:\$00 0800	Reserved
X:\$00 7FFF X:\$00 0040	RESERVED
X:\$00 07FF X:\$00 0000	On-Chip Data RAM ² 4KB

Table 4-4 Data Memory Map¹

1. All addresses are 16-bit Word addresses.

2. This RAM is shared with Program space starting at P: \$00 8000; see Figure 4-1.

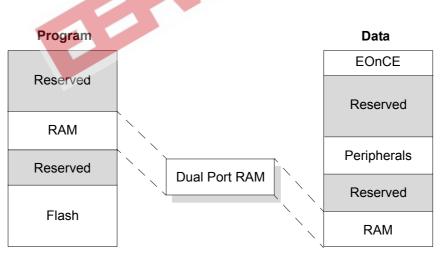


Figure 4-1 Dual Port RAM

4.5 EOnCE Memory Map

Figure 4-5 lists all EOnCE registers necessary to access or control the EOnCE.

Address	Register Acronym	Register Name
X:\$FF FFFF	OTX1 / ORX1	Transmit Register Upper Word Receive Register Upper Word
X:\$FF FFFE	OTX / ORX (32 bits)	Transmit Register Receive Register
X:\$FF FFFD	OTXRXSR	Transmit and Receive Status and Control Register
X:\$FF FFFC	OCLSR	Core Lock / Unlock Status Register
X:\$FF FFFB - X:\$FF FFA1		Reserved
X:\$FF FFA0	OCR	Control Register
X:\$FF FF9F		Instruction Step Counter
X:\$FF FF9E	OSCNTR (24 bits)	Instruction Step Counter
X:\$FF FF9D	OSR	Status Register
X:\$FF FF9C	OBASE	Peripheral Base Address Register
X:\$FF FF9B	OTBCR	Trace Buffer Control Register
X:\$FF FF9A	OTBPR	Trace Buffer Pointer Register
X:\$FF FF99		Trace Buffer Register Stages
X:\$FF FF98	OTB (21 - 24 bits/stage)	Trace Buffer Register Stages
X:\$FF FF97		Breakpoint Unit Control Register
X:\$FF FF96	OBCR (24 bits)	Breakpoint Unit Control Register
X:\$FF FF95		Breakpoint Unit Address Register 1
X:\$FF FF94	OBAR1 (24 bits)	Breakpoint Unit Address Register 1
X:\$FF FF93		Breakpoint Unit Address Register 2
X:\$FF FF92	OBAR2 (32 bits)	Breakpoint Unit Address Register 2
X:\$FF FF91		Breakpoint Unit Mask Register 2
X:\$FF FF90	OBMSK (32 bits)	Breakpoint Unit Mask Register 2
X:\$FF FF8F		Reserved
X:\$FF FF8E	OBCNTR	EOnCE Breakpoint Unit Counter
X:\$FF FF8D		Reserved
X:\$FF FF8C		Reserved
X:\$FF FF8B		Reserved
X:\$FF FF8A	OESCR	External Signal Control Register
X:\$FF FF89 - X:\$FF FF00		Reserved

Table 4-5 EOnCE Memory Map

4.6 Peripheral Memory Mapped Registers

On-chip peripheral registers are part of the data memory map on the 56800E series. These locations may be accessed with the same addressing modes used for ordinary Data memory, except all peripheral registers should be read/written using word accesses only.

Table 4-6 summarizes base addresses for the set of peripherals on the 56F8014 device. Peripherals are listed in order of the base address.

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The following tables list all of the peripheral registers required to control or access the peripherals.

Peripheral	Prefix	Base Address	Table Number
Timer	TMRn	X:\$00 F000	4-7
PWM	PWM	X:\$00 F040	4-8
ITCN	ITCN	X:\$00 F060	4-9
ADC	ADC	X:\$00 F080	4-10
SCI	SCI	X:\$00 F0B0	4-11
SPI	SPI	X:\$00 F0C0	4-12
l ² C	I2C	X:\$00 F0D0	4-13
COP	COP	X:\$00 F0E0	4-14
CLK, PLL, OSC, TEST	OCCS	X:\$00 F0F0	4-15
GPIO Port A	GPIOA	X:\$00 F100	4-16
GPIO Port B	GPIOB	X:\$00 F110	4-17
GPIO Port C	GPIOC	X:\$00 F120	4-18
GPIO Port D	GPIOD	X:\$00 F130	4-19
SIM	SIM	X:\$00 F140	4-20
Power Supervisor	PS	X:\$00 F160	4-21
FM	FM	X:\$00 F400	4-22

 Table 4-6 Data Memory Peripheral Base Address Map Summary

Table 4-7 Quad Timer Registers Address Map (TMR_BASE = \$00 F000)

Register Acronym	Address Offset	Register Description
TMR0_COMP1	\$0	Compare Register 1
TMR0_COMP2	\$1	Compare Register 2
TMR0_CAPT	\$2	Capture Register
TMR0_LOAD	\$3	Load Register
TMR0_HOLD	\$4	Hold Register
TMR0_CNTR	\$5	Counter Register
TMR0_CTRL	\$6	Control Register
TMR0_SCTRL	\$7	Status and Control Register
TMR0_CMPLD1	\$8	Comparator Load Register 1
TMR0_CMPLD2	\$9	Comparator Load Register 2
TMR0_CSCTRL	\$A	Comparator Status and Control Register
		Reserved
TMR1_COMP1	\$10	Compare Register 1
TMR1_COMP2	\$11	Compare Register 2

Register Acronym	Address Offset	Register Description
TMR1_CAPT	\$12	Capture Register
TMR1_LOAD	\$13	Load Register
TMR1_HOLD	\$14	Hold Register
TMR1_CNTR	\$15	Counter Register
TMR1_CTRL	\$16	Control Register
TMR1_SCTRL	\$17	Status and Control Register
TMR1_CMPLD1	\$18	Comparator Load Register 1
TMR1_CMPLD2	\$19	Comparator Load Register 2
TMR1_CSCTRL	\$1A	Comparator Status and Control Register
		Reserved
TMR2_COMP1	\$20	Compare Register 1
TMR2_COMP2	\$21	Compare Register 2
TMR2_CAPT	\$22	Capture Register
TMR2_LOAD	\$23	Load Register
TMR2_HOLD	\$24	Hold Register
TMR2_CNTR	\$25	Counter Register
TMR2_CTRL	\$26	Control Register
TMR2_SCTRL	\$27	Status and Control Register
TMR2_CMPLD1	\$28	Comparator Load Register 1
TMR2_CMPLD2	\$29	Comparator Load Register 2
TMR2_CSCTRL	\$2A	Comparator Status and Control Register
		Reserved
TMR3_COMP1	\$30	Compare Register 1
TMR3_COMP2	\$31	Compare Register 2
TMR3_CAPT	\$32	Capture Register
TMR3_LOAD	\$33	Load Register
TMR3_HOLD	\$34	Hold Register
TMR3_CNTR	\$35	Counter Register
TMR3_CTRL	\$36	Control Register
TMR3_SCTRL	\$37	Status and Control Register
TMR3_CMPLD1	\$38	Comparator Load Register 1
TMR3_CMPLD2	\$39	Comparator Load Register 2
TMR3_CSCTRL	\$3A	Comparator Status and Control Register

Table 4-7 Quad Timer Registers Address Map (Continued) (TMR_BASE = \$00 F000)

Register Acronym	Address Offset	Register Description
PWM_CTRL	\$0	Control Register
PWM_FCTRL	\$1	Fault Control Register
PWM_FLTACK	\$2	Fault Status Acknowledge Register
PWM_OUT	\$3	Output Control Register
PWM_CNTR	\$4	Counter Register
PWM_CMOD	\$5	Counter Modulo Register
PWM_VAL0	\$6	Value Register 0
PWM_VAL1	\$7	Value Register 1
PWM_VAL2	\$8	Value Register 2
PWM_VAL3	\$9	Value Register 3
PWM_VAL4	\$A	Value Register 4
PWM_VAL5	\$B	Value Register 5
PWM_DTIM0	\$C	Dead Time Register 0
PWM_DTIM1	\$D	Dead Time Register 1
PWM_DMAP1	\$E	Disable Mapping Register 1
PWM_DMAP2	\$F	Disable Mapping Register 2
PWM_CNFG	\$10	Configure Register
PWM_CCTRL	\$11	Channel Control Register
PWM_PORT	\$12	Port Register
PWM_ICCTRL	\$13	Internal Correction Control Register
PWM_SCTRL	\$14	Source Control Register

Table 4-8 Pulse Width Modulator Registers Address Map (PWM_BASE = \$00 F040)

Table 4-9 Interrupt Control Registers Address Map (ITCN_BASE = \$00 F060)

Register Acronym	Address Offset	Register Description
ITCN_IPR0	\$0	Interrupt Priority Register 0
ITCN_IPR1	\$1	Interrupt Priority Register 1
ITCN_IPR2	\$2	Interrupt Priority Register 2
ITCN_IPR3	\$3	Interrupt Priority Register 3
ITCN_IPR4	\$4	Interrupt Priority Register 4
ITCN_VBA	\$5	Vector Base Address Register
ITCN_FIM0	\$6	Fast Interrupt Match 0 Register
ITCN_FIVAL0	\$7	Fast Interrupt Vector Address Low 0 Register
ITCN_FIVAH0	\$8	Fast Interrupt Vector Address High 0 Register

Register Acronym	Address Offset	Register Description
ITCN_FIM1	\$9	Fast Interrupt Match 1 Register
ITCN_FIVAL1	\$A	Fast Interrupt Vector Address Low 1 Register
ITCN_FIVAH1	\$B	Fast Interrupt Vector Address High 1 Register
ITCN_IRQP 0	\$C	IRQ Pending Register 0
ITCN_IRQP 1	\$D	IRQ Pending Register 1
ITCN_IRQP 2	\$E	IRQ Pending Register 2
		Reserved
ITCN_ICTRL	\$12	Interrupt Control Register
		Reserved

Table 4-9 Interrupt Control Registers Address Map (Continued) (ITCN_BASE = \$00 F060)

Table 4-10 Analog-to-Digital Converter Registers Address Map (ADC_BASE = \$00 F080)

Register Acronym	Address Offset	Register Description
ADC_CTRL1	\$0	Control Register 1
ADC_CTRL2	\$1	Control Register 2
ADC_ZXCTRL	\$2	Zero Crossing Control Register
ADC_CLIST 1	\$3	Channel List Register 1
ADC_CLIST 2	\$4	Channel List Register 2
ADC_SDIS	\$5	Sample Disable Register
ADC_STAT	\$6	Status Register
ADC_LIMSTAT	\$7	Limit Status Register
ADC_ZXSTAT	\$8	Zero Crossing Status Register
ADC_RSLT0	\$9	Result Register 0
ADC_RSLT1	\$A	Result Register 1
ADC_RSLT2	\$B	Result Register 2
ADC_RSLT3	\$C	Result Register 3
ADC_RSLT4	\$D	Result Register 4
ADC_RSLT5	\$E	Result Register 5
ADC_RSLT6	\$F	Result Register 6
ADC_RSLT7	\$10	Result Register 7
ADC_LOLIM0	\$11	Low Limit Register 0
ADC_LOLIM1	\$12	Low Limit Register 1
ADC_LOLIM2	\$13	Low Limit Register 2
ADC_LOLIM3	\$14	Low Limit Register 3
ADC_LOLIM4	\$15	Low Limit Register 4
ADC_LOLIM5	\$16	Low Limit Register 5

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Table 4-10 Analog-to-Digital Converter Registers Address Map (Continued) (ADC_BASE = \$00 F080)

Register Acronym	Address Offset	Register Description
ADC_LOLIM6	\$17	Low Limit Register 6
ADC_LOLIM7	\$18	Low Limit Register 7
ADC_HILIM0	\$19	High Limit Register 0
ADC_HILIM1	\$1A	High Limit Register 1
ADC_HILIM2	\$1B	High Limit Register 2
ADC_HILIM3	\$1C	High Limit Register 3
ADC_HILIM4	\$1D	High Limit Register 4
ADC_HILIM5	\$1E	High Limit Register 5
ADC_HILIM6	\$1F	High Limit Register 6
ADC_HILIM7	\$20	High Limit Register 7
ADC_OFFST0	\$21	Offset Register 0
ADC_OFFST1	\$22	Offset Register 1
ADC_OFFST2	\$23	Offset Register 2
ADC_OFFST3	\$24	Offset Register 3
ADC_OFFST4	\$25	Offset Register 4
ADC_OFFST5	\$26	Offset Register 5
ADC_OFFST6	\$27	Offset Register 6
ADC_OFFST7	\$28	Offset Register 7
ADC_PWR	\$29	Power Control Register
ADC_VREF	\$2A	Voltage Reference Register
		Reserved

Table 4-11 Serial Communication Interface Registers Address Map (SCI_BASE = \$00 F0B0)

Register Acronym	Address Offset	Register Description
SCI_RATE	\$0	Baud Rate Register
SCI_CTRL1	\$1	Control Register 1
SCI_CTRL2	\$2	Control Register 2
SCI_STAT	\$3	Status Register
SCI_DATA	\$4	Data Register

Table 4-12 Serial Peripheral Interface Registers Address Map (SPI_BASE = \$00 F0C0)

Register Acronym	Address Offset	Register Description
SPI_SCTRL	\$0	Status and Control Register
SPI_DSCTRL	\$1	Data Size and Control Register
SPI_DRCV	\$2	Data Receive Register
SPI_DXMIT	\$3	Data Transmit Register

Table 4-13 I²C Registers Address Map (I2C_BASE = \$00 F0D0)

Register Acronym	Address Offset	Register Description
I2C_ADDR	\$0	Address Register
I2C_FDIV	\$1	Frequency Divider Register
I2C_CTRL	\$2	Control Register
I2C_STAT	\$3	Status Register
I2C_DATA	\$4	Data Register
I2C_NFILT	\$5	Noise Filter Register

Table 4-14 Computer Operating Properly Registers Address Map (COP_BASE = \$00 F0E0)

Register Acronym	Address Offset	Register Description
COP_CTRL	\$0	Control Register
COP_TOUT	\$1	Time-Out Register
COP_CNTR	\$2	Counter Register

Table 4-15 Clock Generation Module Registers Address Map (OCCS_BASE = \$00 F0F0)

Register Acronym	Address Offset	Register Description
OCCS_CTRL	\$0	Control Register
OCCS_DIVBY	\$1	Divide-By Register
OCCS_STAT	\$2	Status Register
		Reserved
OCCS_SHUTDN	\$4	Shutdown Register
OCCS_OCTRL	\$5	Oscillator Control Register

Register Acronym	Address Offset	Register Description
GPIOA_PUPEN	\$0	Pull-up Enable Register
GPIOA_DATA	\$1	Data Register
GPIOA_DDIR	\$2	Data Direction Register
GPIOA_PEREN	\$3	Peripheral Enable Register
GPIOA_IASSRT	\$4	Interrupt Assert Register
GPIOA_IEN	\$5	Interrupt Enable Register
GPIOA_IEPOL	\$6	Interrupt Edge Polarity Register
GPIOA_IPEND	\$7	Interrupt Pending Register
GPIOA_IEDGE	\$8	Interrupt Edge-Sensitive Register
GPIOA_PPOUTM	\$9	Push-Pull Output Mode Control Register
GPIOA_RDATA	\$A	Raw Data Register
GPIOA_DRIVE	\$B	Drive Strength Control Register
	3	3 B M.C.

Table 4-16 GPIOA Registers Address Map (GPIOA_BASE = \$00 F100)

Table 4-17 GPIOB Registers Address Map (GPIOB_BASE = \$00 F110)

Register Acronym	Address Offset	Register Description
GPIOB_PUPEN	\$0	Pull-up Enable Register
GPIOB_DATA	\$1	Data Register
GPIOB_DDIR	\$2	Data Direction Register
GPIOB_PEREN	\$3	Peripheral Enable Register
GPIOB_IASSRT	\$4	Interrupt Assert Register
GPIOB_IEN	\$5	Interrupt Enable Register
GPIOB_IEPOL	\$6	Interrupt Edge Polarity Register
GPIOB_IPEND	\$7	Interrupt Pending Register
GPIOB_IEDGE	\$8	Interrupt Edge-Sensitive Register
GPIOB_PPOUTM	\$9	Push-Pull Output Mode Control Register
GPIOB_RDATA	\$A	Raw Data Register
GPIOB_DRIVE	\$B	Drive Strength Control Register

Table 4-18 GPIOC Registers Address Map (GPIOC_BASE = \$00 F120)

Register Acronym	Address Offset	Register Description	
GPIOC_PUPEN	\$0	Pull-up Enable Register	
GPIOC_DATA	\$1	Data Register	
GPIOC_DDIR	\$2	Data Direction Register	
GPIOC_PEREN	\$3	Peripheral Enable Register	
GPIOC_IASSRT	\$4	Interrupt Assert Register	
GPIOC_IEN	\$5	Interrupt Enable Register	
GPIOC_IEPOL	\$6	Interrupt Edge Polarity Register	
GPIOC_IPEND	\$7	Interrupt Pending Register	
GPIOC_IEDGE	\$8	Interrupt Edge-Sensitive Register	
GPIOC_PPOUTM	\$9	Push-Pull Output Mode Control Register	
GPIOC_RDATA	\$A	Raw Data Register	
GPIOC_DRIVE	\$B	Drive Strength Control Register	
Table 4-19 GPIOD Pergisters Address Man			

Table 4-19 GPIOD Registers Address Map (GPIOD_BASE = \$00 F130)

Register Acronym	Address Offset	Register Description
GPIOD_PUPEN	\$0	Pull-up Enable Register
GPIOD_DATA	\$1	Data Register
GPIOD_DDIR	\$2	Data Direction Register
GPIOD_PEREN	\$3	Peripheral Enable Register
GPIOD_IASSRT	\$4	Interrupt Assert Register
GPIOD_IEN	\$5	Interrupt Enable Register
GPIOD_IEPOL	\$6	Interrupt Edge Polarity Register
GPIOD_IPEND	\$7	Interrupt Pending Register
GPIOD_IEDGE	\$8	Interrupt Edge-Sensitive Register
GPIOD_PPOUTM	\$9	Push-Pull Output Mode Control Register
GPIOD_RDATA	\$A	Raw Data Register
GPIOD_DRIVE	\$B	Drive Strength Control Register

Register Acronym	Address Offset	Register Description
SIM_CTRL	\$0	Control Register
SIM_RSTAT	\$1	Reset Status Register
SIM_SWC0	\$2	Software Control Register 0
SIM_SWC1	\$3	Software Control Register 1
SIM_SWC2	\$4	Software Control Register 2
SIM_SWC3	\$5	Software Control Register 3
SIM_MSHID	\$6	Most Significant Half JTAG ID
SIM_LSHID	\$7	Least Significant Half JTAG ID
SIM_PWR	\$8	Power Control Register
		Reserved
SIM_CLKOUT	\$A	Clock Out Select Register
SIM_GPS	\$B	GPIO Peripheral Select Register
SIM_PCE	\$C	Peripheral Clock Enable Register
SIM_IOSAHI	\$D	I/O Short Address Location High Register
SIM_IOSALO	\$E	I/O Short Address Location Low Register

Table 4-20 System Integration Module Registers Address Map (SIM_BASE = \$00 F140)

Table 4-21 Power Supervisor Registers Address Map (PS_BASE = \$00 F160)

Register Acronym	Address Offset	Register Description
PS_CTRL	\$0	Control Register
PS_STAT	\$1	Status Register

Table 4-22 Flash Module Registers Address Map (FM_BASE = \$00 F400)

Register Acronym	Address Offset	Register Description
FM_CLKDIV	\$0	Clock Divider Register
FM_CNFG	\$1	Configuration Register
	\$2	Reserved
FM_SECHI	\$3	Security High Half Register
FM_SECLO	\$4	Security Low Half Register
	\$5 - \$9	Reserved
FM_PROT	\$10	Protection Register
	\$11 - \$12	Reserved

Register Acronym	Address Offset	Register Description
FM_USTAT	\$13	User Status Register
FM_CMD	\$14	Command Register
	\$15	Reserved
	\$16	Reserved
	\$17	Reserved
FM_DATA	\$18	Data Buffer Register
	\$19	Reserved
	\$1A	Reserved
FM_OPT1	\$1B	Optional Data 1 Register
		Reserved
FM_TSTSIG	\$1D	Test Array Signature Register

Table 4-22 Flash Module Registers Address Map (Continued) (FM BASE = \$00 F400)

Part 5 Interrupt Controller (ITCN)

The Interrupt Controller (ITCN) module is used to arbitrate between various interrupt requests (IRQs), to signal to the 56800E core when an interrupt of sufficient priority exists, and to what address to jump in order to service this interrupt.

5.2 Features

The ITCN module design includes these distinctive features:

- Programmable priority levels for each IRQ
- ٠ Two programmable Fast Interrupts
- Notification to SIM module to restart clocks out of Wait and Stop modes
- Ability to drive initial address on the address bus after reset

For further information, see Table 4-2, Interrupt Vector Table Contents.

Functional Description 5.3

The Interrupt Controller is a slave on the IPBus. It contains registers that allow each of the 46 interrupt sources to be set to one of four priority levels (excluding certain interrupts that are of fixed priority). Next, all of the interrupt requests of a given level are priority encoded to determine the lowest numerical value of the active interrupt requests for that level. Within a given priority level, number 0 is the highest priority and number 45 is the lowest.

5.3.1 Normal Interrupt Handling

Once the INTC has determined that an interrupt is to be serviced and which interrupt has the highest priority, an interrupt vector address is generated. Normal interrupt handling concatenates the Vector Base Address (VBA) and the vector number to determine the vector address, generating an offset into the vector table for each interrupt.

5.3.2 Interrupt Nesting

Interrupt exceptions may be nested to allow an IRQ of higher priority than the current exception to be serviced. The following table defines the nesting requirements for each priority level.

SR[9]	SR[8]	Exceptions Permitted	Exceptions Masked
0	0	Priorities 0, 1, 2, 3	None
0	1	Priorities 1, 2, 3	Priority 0
1	0	Priorities 2, 3	Priorities 0, 1
1	1	Priority 3	Priorities 0, 1, 2

Table 5-1 Interrupt Mask Bit Definition

5.3.3 Fast Interrupt Handling

Fast interrupts are described in the **DSP56800E Reference Manual**. The interrupt controller recognizes Fast Interrupts before the core does.

A Fast Interrupt is defined (to the ITCN) by:

- 1. Setting the priority of the interrupt as level 2, with the appropriate field in the IPR registers
- 2. Setting the FIMn register to the appropriate vector number
- 3. Setting the FIVAL*n* and FIVAH*n* registers with the address of the code for the Fast Interrupt

When an interrupt occurs, its vector number is compared with the FIM0 and FIM1 register values. If a match occurs, and it is a level 2 interrupt, the ITCN handles it as a Fast Interrupt. The ITCN takes the vector address from the appropriate FIVAL*n* and FIVAH*n* registers, instead of generating an address that is an offset from the VBA.

The core then fetches the instruction from the indicated vector adddress and if it is not a JSR, the core starts its Fast Interrupt handling.

Block Diagram

5.4 Block Diagram

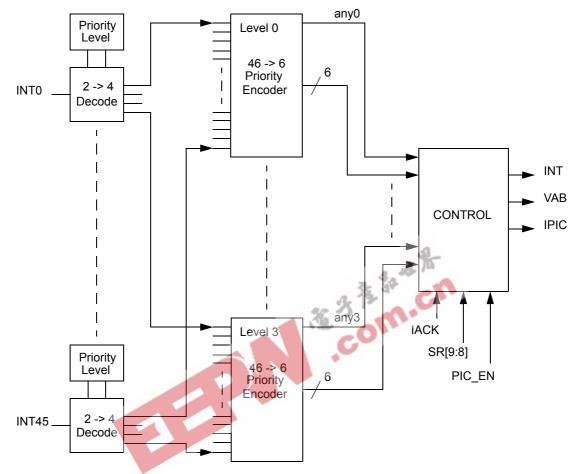


Figure 5-1 Interrupt Controller Block Diagram

5.5 Operating Modes

The ITCN module design contains two major modes of operation:

• Functional Mode

The ITCN is in this mode by default.

• Wait and Stop Modes During Wait and Stop modes, the system clocks and the 56800E core are turned off. The ITCN will signal a pending IRQ to the System Integration Module (SIM) to restart the clocks and service the IRQ. An IRQ can only wake up the core if the IRQ is enabled prior to entering the Wait or Stop mode.

5.6 Register Descriptions

A register address is the sum of a base address and an address offset. The base address is defined at the system level and the address offset is defined at the module level. The ITCN module has 16 registers.

Register Acronym	Base Address +	Register Name	Section Location
IPR0	\$0	Interrupt Priority Register 0	5.6.1
IPR1	\$1	Interrupt Priority Register 1	5.6.2
IPR2	\$2	Interrupt Priority Register 2	5.6.3
IPR3	\$3	Interrupt Priority Register 3	5.6.4
IPR4	\$4	Interrupt Priority Register 4	5.6.5
VBA	\$5	Vector Base Address Register	5.6.6
FIM0	\$6	Fast Interrupt Match 0 Register	5.6.7
FIVAL0	\$7	Fast Interrupt 0 Vector Address Low Register	5.6.8
FIVAH0	\$8	Fast Interrupt 0 Vector Address High Register	5.6.9
FIM1	\$9	Fast Interrupt Match 1 Register	5.6.10
FIVAL1	\$A	Fast Interrupt 1 Vector Address Low Register	5.6.11
FIVAH1	\$B	Fast Interrupt 1 Vector Address High Register	5.6.12
IRQP0	\$C	IRQ Pending Register 0	5.6.13
IRQP1	\$D	IRQ Pending Register 1	5.6.14
IRQP2	\$E	IRQ Pending Register 2	5.6.15
		Reserved	
ICTRL	\$12	Interrupt Control Register	5.6.16
		Reserved	

Table 5-2 ITCN Register Summary (ITCN_BASE = \$00 F060)

Register Descriptions

Add. Offset	Register Name		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
\$0	IPR0	R W	LVI	IPL	0	0	0	0	RX_RE	EG IPL	TX_RE	EG IPL	TRBL	IF IPL	BKP	T_U IPL	STPC	NT IPL		
\$1	IPR1	R W	GPIC	B IPL	GPIO	CIPL	GPIO	D IPL	0	0	FM_CI	BE IPL	FM_C	C IPL	FM_I	ERR IPL	PLI	l IPL		
\$2	IPR2	R W		RCV L		RERR PL	0	0	SCI_TI	DLIPL	SCI_ IF	XMIT YL	SPI_XMIT IPL SPI_RCV IPL GPIOA IP							
\$3	IPR3	R W		A_CC PL	TMR_	_3 IPL	TMR_	2 IPL	TMR_	1 IPL	TMR_	0 IPL	I2C_A IF		0	0	0	0		
\$4	IPR4	R W	0	0	0	0	0	0	0	0	PWM_	_F IPL	PWM_	RL IPL	ADC	_ZC_LE IPL	ADCB	_CC IPL		
\$5	VBA	R W	0	0						VEC	TOR_B	ASE_A	DDRESS	3						
\$6	FIM0	R W	0	0	0	0	0	0	0	0	0	0		I	FAST IN	ITERRUP	ГО			
\$7	FIVAL0	R W						FAST	INTERF	RUPT 0	VECTO	R ADDF	RESSLO	w						
\$8	FIVAH0	R W	0	0	0	0	0	0	0	0	0	0	-	F.		TERRUPT DDRESS H		OR		
\$9	FIM1	R W	0	0	0	0	0	0	0	0		0	cX.		FAST IN	NTERRUP	Г 1			
\$A	FIVAL1	R W						FAST	INTERF	RUPT 1	VECTO	RADDR	RESS LC	W						
\$В	FIVAH1	R W	0	0	0	0	0		0	0	0	0	0	FA		ERRUPT		ΓOR		
\$C	IRQP0	R W				-			PE	NDING	[16:2]							1		
\$D	IRQP1	R W								PEND	ING[32:"	17]								
\$E	IRQP2	R W	1		1						PE	NDING	[45:33]							
	Reserved																			
\$12	ICTRL	R W	INT	IP	IC				VAB				INT_ DIS	1	1	1	0	0		
	Reserved																			
				= Rese	erved															

Figure 5-2 ITCN Register Map Summary

5.6.1 Interrupt Priority Register 0 (IPR0)

Base + \$0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	I VI	IPL	0	0	0	0	RX RE	GIPI	TX RE	GIPI	TRBL	IF IPI	вкрт		STPCI	
Write							10.		17_1		INDO		DIVI 1_	_0 L	011 01	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-3 Interrupt Priority Register 0 (IPR0)

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5.6.1.1 LVI IPL—Bits 15–14

This field is used to set the interrupt priority levels for a peripheral IRQ. This IRQ is limited to priorities 0 through 2 and is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2 ٠

5.6.1.2 Reserved—Bits 13–10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.1.3 EOnCE Receive Register Full Interrupt Priority Level (RX REG IPL)— Bits 9-8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. · COM·CI It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRO is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.1.4 EOnCE Transmit Register Empty Interrupt Priority Level (TX REG IPL)— Bits 7-6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1 •
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.1.5 EOnCE Trace Buffer Interrupt Priority Level (TRBUF IPL)— Bits 5-4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRO is priority level 3

EOnCE Breakpoint Unit Interrupt Priority Level 5.6.1.6 (BKPT U IPL)— Bits 3-2

This field is used to set the interrupt priority level for IROs. This IRO is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3 ٠

5.6.1.7 EOnCE Step Counter Interrupt Priority Level (STPCNT IPL)— Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1 •
- 10 = IRQ is priority level 2 ٠
- 11 = IRQ is priority level 3 •

5.6.2 Interrupt Priority Register 1 (IPR1)

 00 = IRQ 01 = IRQ 10 = IRQ 11 = IRQ 	is pric is pric is prio	ority le ority le ority le	evel 1 evel 2 evel 3		egist	:e r 1	(IPI		落	1 1 1 1 1	S.					
Base + \$1	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	GPIC	B IPL	GPIC		GPIO		0	0	FM C	BE IPL	FM (FM EI	RR IPI	PLL	IPI
Write									0							
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-4 Interrupt Priority Register 1 (IPR1)

GPIOB Interrupt Priority Level (GPIOB IPL)—Bits 15–14 5.6.2.1

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- ٠ 11 = IRQ is priority level 2

5.6.2.2 GPIOC Interrupt Priority Level (GPIOC IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

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5.6.2.3 GPIOD Interrupt Priority Level (GPIOD IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2 ٠

5.6.2.4 Reserved—Bits 9–8

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.2.5 FM Command, Data, Address Buffers Empty Interrupt Priority Level (FM CBE IPL)—Bits 7-6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2 •

FM Command Complete Priority Level (FM CC IPL)—Bits 5-4 5.6.2.6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRO disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.2.7 FM Error Interrupt Priority Level (FM ERR IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.2.8 PLL Loss of Reference or Change in Lock Status Interrupt Priority Level (PLL IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3 Interrupt Priority Register 2 (IPR2)

Base + \$2	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	SCI P	CV IPL	SCI_F		0	0	SCI TI	וסו וח	SCI XI		SDI YN		SPI R		GPIO	A IPL
Write	001_1		IF	۲L			001_11		00I_XI	VIII II L	011_71	vii i L			0110	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-5 Interrupt Priority Register 2 (IPR2)

5.6.3.1 SCI Receiver Full Interrupt Priority Level (SCI_RCV IPL)— Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.2 SCI Receiver Error Interrupt Priority Level (SCI_RERR IPL)— Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.3 Reserved—Bits 11–10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

SCI Transmitter Idle Interrupt Priority Level (SCI TIDL IPL)-5.6.3.4 Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2 ٠

5.6.3.5 SCI Transmitter Empty Interrupt Priority Level (SCI XMIT IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1 ٠
- 11 = IRQ is priority level 2 ٠

IRQ is priority level 0 IRQ is priority level 1 IRQ is priority level 2 SPI Transmitter Empty Interrupt Priority Level (SPI_XMIT IPL)— 5.6.3.6 Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default) •
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1 ٠
- 11 = IRQ is priority level 2

5.6.3.7 SPI Receiver Full Interrupt Priority Level (SPI_RCV IPL)— Bits 3-2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.8 GPIOA Interrupt Priority Level (GPIOA IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4 Interrupt Priority Register 3 (IPR3)

Base + \$3	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read		CC IPL	TMR	3 IPI	TMR	2 IPI	TMR	1 IPL	TMR	0 IPI	12C_A		0	0	0	0
Write	ADOA_	00112									IPL					
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-6 Interrupt Priority Register 3 (IPR3)

5.6.4.1 ADCA Conversion Complete Interrupt Priority Level (ADCA_CC IPL)—Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.2 Timer Channel 3 Interrupt Priority Level (TMR_3 IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.3 Timer Channel 2 Interrupt Priority Level (TMR_2 IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.4 Timer Channel 1 Interrupt Priority Level (TMR_1 IPL)—Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.5 Timer Channel 0 Interrupt Priority Level (TMR_0 IPL)—Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.6 I²C Address Detect Interrupt Priority Level (I2C ADDR IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

. A. R.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.7 Reserved—Bits 3–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.5 Interrupt Priority Register 4 (IPR4)

Base + \$4	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0			PWM	RI IPI	ADC_2		ADCB_CC	
Write									PWM_F IPL				IP	Ľ	IF	Ľ
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-7 Interrupt Priority Register 4 (IPR4)

5.6.5.1 Reserved—Bits 15-8

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

PWM Fault Interrupt Priority Level (PWM F IPL)— 5.6.5.2 Bits 7–6

This field is used to set the interrupt priority level for IROs. This IRO is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2 ٠

5.6.5.3 Reload PWM Interrupt Priority Level (PWM RL IPL)— Bits 5-4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1 ٠
- 11 = IRQ is priority level 2 ٠

or Intern ADC Zero Crossing or Limit Error Interrupt Priority Level 5.6.5.4 (ADC ZC LE IPL)-Bits 3-2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default) •
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.5 ADCB Conversion Complete Interrupt Priority Level (ADCB CC IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0 •
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6 Vector Base Address Register (VBA)

Base + \$5	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0						VECTO	OR BAS		RESS					
Write								VLOIC			LOO					
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-8 Vector Base Address Register (VBA)

5.6.6.1 Reserved—Bits15—14

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.6.2 Vector Address Bus (VAB)—Bits 13—0

The value in this register is used as the upper 14 bits of the interrupt vector VAB[20:0]. The lower 7 bits are determined based on the highest priority interrupt and are then appended onto VBA before presenting the full VAB to the Core.

5.6.7 Fast Interrupt Match 0 Register (FIM0)

			-	-			-		<u> </u>	S				-	-	
Base + \$6	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0		FA	AST INTI		0	
Write								(ŝ			.,			Ū	
RESET	0	0	0	0	0	0	0	0 🥠	0	0	0	0	0	0	0	0

Figure 5-9 Fast Interrupt Match 0 Register (FIM0)

5.6.7.1 Reserved—Bits 15-6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.7.2 Fast Interrupt 0 Vector Number (FAST INTERRUPT 0)—Bits 5–0

These values determine which IRQ will be Fast Interrupt 0. Fast Interrupts vector directly to a service routine based on values in the Fast Interrupt Vector Address registers without having to go to a jump table first. IRQs used as Fast Interrupts *must* be set to priority level 2. Unexpected results will occur if a Fast Interrupt vector is set to any other priority. A Fast Interrupt automatically becomes the highest-priority level 2 interrupt regardless of its location in the interrupt table prior to being declared as Fast Interrupt. Fast Interrupt 0 has priority over fast Interrupt 1. To determine the vector number of each IRQ, refer to the vector table.

5.6.8 Fast Interrupt 0 Vector Address Low Register (FIVAL0)

Base + \$7	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read						FAST IN					NO L 22					
Write						I AGT II	TLARU	FIUVL			53 LOW					
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-10 Fast Interrupt 0 Vector Address Low Register (FIVAL0)

56F8014 Technical Data, Rev. 9

5.6.8.1 Fast Interrupt 0 Vector Address Low (FIVAL0)—Bits 15—0

The lower 16 bits of the vector address used for Fast Interrupt 0. This register is combined with FIVAH0 to form the 21-bit vector address for Fast Interrupt 0 defined in the FIM0 register.

5.6.9 Fast Interrupt 0 Vector Address High Register (FIVAH0)

Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	FA	ST INTE			OR
Write													ADD	RESS H	ligh	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-11 Fast Interrupt 0 Vector Address High Register (FIVAH0)

5.6.9.1 Reserved—Bits 15–5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.9.2 Fast Interrupt 0 Vector Address High (FIVAH0)-Bits 4–0

The upper five bits of the vector address used for Fast Interrupt 0. This register is combined with FIVAL0 to form the 21-bit vector address for Fast Interrupt 0 defined in the FIM0 register.

5.6.10 Fast Interrupt 1 Match Register (FIM1)

Base + \$9	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0		FAST INTERRUPT 1				
Write					. <										•	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-12 Fast Interrupt 1 Match Register (FIM1)

5.6.10.1 Reserved—Bits 15-6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.10.2 Fast Interrupt 1 Vector Number (FAST INTERRUPT 1)—Bits 5–0

These values determine which IRQ will be Fast Interrupt 1. Fast Interrupts vector directly to a service routine based on values in the Fast Interrupt Vector Address registers without having to go to a jump table first. IRQs used as Fast Interrupts *must* be set to priority level 2. Unexpected results will occur if a Fast Interrupt vector is set to any other priority. A Fast Interrupt automatically becomes the highest-priority level 2 interrupt regardless of its location in the interrupt table prior to being declared as Fast Interrupt. Fast Interrupt 0 has priority over Fast Interrupt 1. To determine the vector number of each IRQ, refer to the vector table.

5.6.11 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

Base + \$A	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read		FAST INTERRUPT 1 VECTOR ADDRESS LOW														
Write						1 AUT III			.0101(7							
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-13 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

5.6.11.1 Fast Interrupt 1 Vector Address Low (FIVAL1)—Bits 15–0

The lower 16 bits of the vector address used for Fast Interrupt 1. This register is combined with FIVAH1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.12 Fast Interrupt 1 Vector Address High Register (FIVAH1)

Base + \$B	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	FA	ST INTE			OR
Write											175		ADD	RESS F	ligh	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-14 Fast Interrupt 1 Vector Address High Register (FIVAH1)

5.6.12.1 Reserved—Bits 15–5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.12.2 Fast Interrupt 1 Vector Address High (FIVAH1)—Bits 4–0

The upper five bits of the vector address are used for Fast Interrupt 1. This register is combined with FIVAL1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.13 IRQ Pending Register 0 (IRQP0)

Base + \$C	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read							PEN	IDING[1	6:2]							1
Write																
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 5-15 IRQ Pending Register 0 (IRQP0)

5.6.13.1 IRQ Pending (PENDING)—Bits 15–1

This register combines with IRQP1 and IRQP2 to represent the pending IRQs for interrupt vector numbers 2 through 45.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.13.2 Reserved—Bit 0

This bit is reserved or not implemented. It is read as 1 and cannot be modified by writing.

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5.6.14 IRQ Pending Register 1 (IRQP1)

Base + \$D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read								PENDIN	G[32:17]						
Write																
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 5-16 IRQ Pending Register 1 (IRQP1)

5.6.14.1 IRQ Pending (PENDING)—Bits 32–17

This register combines with IRQP0 and IRQP2 to represent the pending IRQs for interrupt vector numbers 2 through 45.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.15 IRQ Pending Register 2 (IRQP2)

											Sec. 1					
Base + \$E	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	1	1	1						PEN	DING[4	5:33]					
Write								20 1	51							
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

1

Figure 5-17 IRQ Pending Register 2 (IRQP2)

5.6.15.1 IRQ Pending (PENDING)--Bits 45-33

This register combines with IRQP0 and IRQP1 to represent the pending IRQs for interrupt vector numbers 2 through 45.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.16 Interrupt Control Register (ICTRL)

\$Base + \$12	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	INT	IP	IC				VAB				INT_	1	1	1	0	0
Write											DIS					
RESET	0	0	0	0	0	0	0	0	0	0	0	1	1	1	0	0

Figure 5-18 Interrupt Control Register (ICTRL)

5.6.16.1 Interrupt (INT)—Bit 15

This *read-only* bit reflects the state of the interrupt to the 56800E core.

- 0 = No interrupt is being sent to the 56800E core
- 1 = An interrupt is being sent to the 56800E core

5.6.16.2 Interrupt Priority Level (IPIC)—Bits 14–13

These *read-only* bits reflect the state of the new interrupt priority level bits being presented to the 56800E core. These bits indicate the priority level needed for a new IRQ to interrupt the current interrupt being sent to the 56800E core. This field is only updated when the 56800E core jumps to a new interrupt service routine.

Note: Nested interrupts may cause this field to be updated before the original interrupt service routine can read it.

- 00 = Required nested exception priority levels are 0, 1, 2, or 3
- 01 = Required nested exception priority levels are 1, 2, or 3
- 10 = Required nested exception priority levels are 2 or 3
- 11 = Required nested exception priority level is 3

IPIC_VALUE[1:0]	Current Interrupt Priority Level	Required Nested Exception Priority
00	No interrupt or SWILP	Priorities 0, 1, 2, 3
01	Priority 0	Priorities 1, 2, 3
10	Priority 1	Priorities 2, 3
11	Priority 2 or 3	Priority 3

Table 5-3 Interrupt Priority Encoding

5.6.16.3 Vector Number - Vector Address Bus (VAB)—Bits 12–6

This *read-only* field shows the vector number (VAB[6:0]) used at the time the last IRQ was taken. In the case of a Fast Interrupt, it shows the lower address bits of the jump address. This field is only updated when the 56800E core jumps to a new interrupt service routine.

Note: Nested interrupts may cause this field to be updated before the original interrupt service routine can read it.

5.6.16.4 Interrupt Disable (INT_DIS)—Bit 5

This bit allows all interrupts to be disabled.

- 0 = Normal operation (default)
- 1 = All interrupts disabled

5.6.16.5 Reserved—Bits 4–2

This bit field is reserved or not implemented. It is read as 1 and cannot be modified by writing.

5.6.16.6 Reserved—Bits 1–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

Resets

5.7 Resets

5.7.1 General

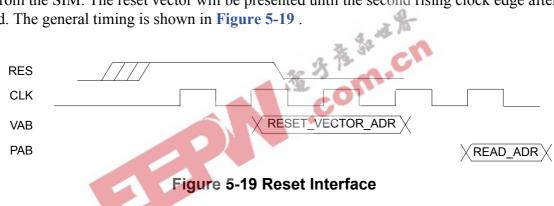
Table 5-4 Reset Summary

Reset	Priority	Source	Characteristics
Core Reset		RST	Core reset from the SIM

5.7.2 Description of Reset Operation

5.7.2.1 Reset Handshake Timing

The ITCN provides the 56800E core with a reset vector address on the VAB pins whenever $\overline{\text{RESET}}$ is asserted from the SIM. The reset vector will be presented until the second rising clock edge after $\overline{\text{RESET}}$ is released. The general timing is shown in Figure 5-19.



5.7.3 ITCN After Reset

After reset, all of the ITCN registers are in their default states. This means all interrupts are disabled, except the core IRQs with fixed priorities:

- Illegal Instruction
- SW Interrupt 3
- HW Stack Overflow
- Misaligned Long Word Access
- SW Interrupt 2
- SW Interrupt 1
- SW Interrupt 0
- SW Interrupt LP

These interrupts are enabled at their fixed priority levels.

Part 6 System Integration Module (SIM)

Introduction 6.1

The SIM module is a system catchall for the glue logic that ties together the system-on-chip. It controls distribution of resets and clocks and provides a number of control features. The System Integration Module is responsible for the following functions:

- Reset sequencing
- . Clock control & distribution
- Stop/Wait control
- System status registers
- Registers for software access to the JTAG ID of the chip
- Test registers •
- Power control •
- I/O pad multiplexing ٠

·com.cn These are discussed in more detail in the sections that follow

6.2 Features

The SIM has the following features:

- System bus clocks with pipeline hold-off support •
- System clocks for non-pipelined interfaces
- Peripheral clocks for TMR and PWM with high-speed (3X) option
- Power-saving clock gating for peripherals
- ITCK clock to the 56800E core TAP interface •
- Three power modes (Run, Wait, Stop) to control power utilization •
 - Stop mode shuts down the 56800E core, system clock, and peripheral clock
 - Wait mode shuts down the 56800E core and unnecessary system clock operation
 - Run mode supports full part operation
- Controls, with write protection, the enable/disable of 56800E core WAIT and STOP instructions
- Controls, with write protection, the enable/disable of Large Regulator Standby mode •
- Controls to route functional signals to selected peripherals and I/O pads •
- Controls deassertion sequence of internal resets •
- Software-initiated reset
- Four 16-bit registers reset only by a Power-On Reset usable for general-purpose software control
- ٠ Timer channel Stop mode clocking controls
- SCI Stop mode clocking control to support LIN Sleep mode stop recovery
- Short addressing location control
- Registers for software access to the JTAG ID of the chip •
- Controls output to CLKO pin

6.3 Register Descriptions

_CTRL _RSTAT _SWC0 _SWC1 _SWC2 _SWC3 _MSHID _LSHID _LSHID PWR	Control Register Reset Status Register Software Control Register 0 Software Control Register 1 Software Control Register 2 Software Control Register 3 Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.1 6.3.2 6.3.3 6.3.3 6.3.3 6.3.3 6.3.3 6.3.4 6.3.5
SWC0 _SWC1 _SWC2 _SWC3 _MSHID _LSHID	Software Control Register 0 Software Control Register 1 Software Control Register 2 Software Control Register 3 Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.3 6.3.3 6.3.3 6.3.3 6.3.4
	Software Control Register 1 Software Control Register 2 Software Control Register 3 Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.3 6.3.3 6.3.3 6.3.4
_SWC2 _SWC3 _MSHID _LSHID	Software Control Register 2 Software Control Register 3 Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.3 6.3.3 6.3.4
_SWC3 _MSHID _LSHID	Software Control Register 3 Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.3 6.3.4
_MSHID _LSHID	Most Significant Half of JTAG ID Least Significant Half of JTAG ID	6.3.4
_LSHID	Least Significant Half of JTAG ID	
		6.3.5
ם/עם		
PVVR	Power Control Register	6.3.6
	Reserved	
CLKOUT	CLKO Select Register	6.3.7
GPS	GPIO Peripheral Select Register	6.3.8
PCE	Peripheral Clock Enable Register	6.3.9
IOSAHI	VO Short Address Location High Register	6.3.10
IOSALO	I/O Short Address Location Low Register	6.3.10
	_GPS _PCE _IOSAHI	CLKOUT CLKO Select Register GPS GPIO Peripheral Select Register PCE Peripheral Clock Enable Register IOSAHI VO Short Address Location High Register

Table 6-1 SIM Registers (SIM_BASE = \$00 F140)



Add. Offset	Address Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	SIM_ CTRL	R W	TC3_ SD	TC2_ SD	TC1_ SD	TC0_ SD	SCI_ SD	0	TC3_ INP	0	0	0	ONCE EBL	SW RST	STO DISA	DP_ ABLE	WA DISA	
\$1	SIM_ RSTAT	R W	0	0	0	0	0	0	0	0	0	0	SWR	COPR	EXTR	POR	0	0
\$2	SIM_SWC0	R W							Sof	tware Co	ontrol Dat	a 0						
\$3	SIM_SWC1	R W							Sof	tware Co	ontrol Dat	a 1						
\$4	SIM_SWC2	R W							Sof	tware Co	ontrol Dat	a 2						
\$5	SIM_SWC3	R W							Sof	tware Co	ontrol Dat	a 3						
\$6	SIM_MSHID	R W	0	0	0	0	0	0	0	1	1	1	1	1	0	0	1	0
\$7	SIM_LSHID	R W	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1
\$8	SIM_PWR	R W	0	0	0	0	0	0	0	0	0	0		0	0	0	LRST	DBY
	Reserved										7. 7	4						
\$A	SIM_ CLKOUT	R W	0	0	0	0	0	0	PWM3	PWM2	PWM1	PWM0	CLK DIS		C	LKOSEI	L	
\$В	SIM_GPS	R W	TCR	PCR	0	0	CFG_ B7	CFG_ B6	CFG_ B5	CFG_ B4	CFG_ B3	CFG_ B2	CFG_ B1	CFG_ B0	CFG	i_A5	CFG	_A4
\$C	SIM_PCE	R W	I2C	0	ADC	0		0	0		0	TMR	0	SCI	0	SPI	0	PWM
\$D	SIM_IOSAHI	R W	0	0	0	0		0	0	0	0	0	0	0	0	0	ISAL[2	23:22]
\$E	SIM_IOSALO	R W	ISAI [21:6]															
			0	= Read = Reser			1	= Read = Rese										

Figure 6-1 SIM Register Map Summary

6.3.1 SIM Control Register (SIM_CTRL)

Base + \$0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	TC3_	TC2_	TC1_	TC0_	SCI_	0	TC3_	0	0	0	ONCE	SW	STO		WA	
Write	SD	SD	SD	SD	SD		INP				EBL	RST	DISA	BLE	DISA	BLE
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-2 SIM Control Register (SIM_CTRL)

6.3.1.1 Timer Channel 3 Stop Disable (TC3_SD)—Bit 15

This bit enables the operation of the Timer Channel 3 peripheral clock in Stop mode.

- 0 = Timer Channel 3 disabled in Stop mode
- 1 = Timer Channel 3 enabled in Stop mode

6.3.1.2 Timer Channel 2 Stop Disable (TC2_SD)—Bit 14

This bit enables the operation of the Timer Channel 2 peripheral clock in Stop mode.

- 0 = Timer Channel 2 disabled in Stop mode
- 1 = Timer Channel 2 enabled in Stop mode

6.3.1.3 Timer Channel 1 Stop Disable (TC1_SD)—Bit 13

This bit enables the operation of the Timer Channel 1 peripheral clock in Stop mode.

- 0 = Timer Channel 1 disabled in Stop mode
- 1 = Timer Channel 1 enabled in Stop mode

6.3.1.4 Timer Channel 0 Stop Disable (TC0_SD)—Bit 12

This bit enables the operation of the Timer Channel 0 peripheral clock in Stop mode.

- 0 = Timer Channel 0 disabled in Stop mode
- 1 = Timer Channel 0 enabled in Stop mode

6.3.1.5 SCI Stop Disable (SCI_SD)—Bit 11

This bit enables the operation of the SCI peripheral clock in Stop mode. This is recommended for use in LIN mode so that the SCI can generate interrupts and recover from Stop mode while the LIN interface is in Sleep mode and using Stop mode to reduce power consumption.

30 × 8

- 0 = SCI disabled in Stop mode
- 1 = SCI enabled in Stop mode

6.3.1.6 Reserved—Bit 10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.1.7 Timer Channel 3 Input (TC3_INP)—Bit 9

This bit selects the input of Timer Channel 3 to be from the PWM or GPIO.

- 1 = Timer Channel 3 Input from PWM reload_sync signal
- 0 = Timer Channel 3 Input controlled by SIM_GPS register CFG_B3 and CFG_A5 fields

6.3.1.8 Reserved—Bits 8–6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.1.9 OnCE Enable (ONCEEBL)—Bit 5

- 0 = OnCE clock to 56800E core enabled when core TAP is enabled
- 1 = OnCE clock to 56800E core is always enabled

6.3.1.10 Software Reset (SWRST)—Bit 4

Writing 1 to this field will cause the part to reset.

6.3.1.11 Stop Disable (STOP_DISABLE[1:0])—Bits 3–2

- 00 = Stop mode will be entered when the 56800E core executes a STOP instruction
- 01 = The 56800E STOP instruction will not cause entry into Stop mode
- 10 = Stop mode will be entered when the 56800E core executes a STOP instruction and the STOP_DISABLE field is write-protected until the next reset
- 11 = The 56800E STOP instruction will not cause entry into Stop mode and the STOP_DISABLE field is write-protected until the next reset

6.3.1.12 Wait Disable (WAIT_DISABLE[1:0])—Bits 1–0

- 00 = Wait mode will be entered when the 56800E core executes a WAIT instruction
- 01 = The 56800E WAIT instruction will not cause entry into Wait mode
- 10 = Wait mode will be entered when the 56800E core executes a WAIT instruction and the WAIT_DISABLE field is write-protected until the next reset
- 11 = The 56800E WAIT instruction will not cause entry into Wait mode and the WAIT_DISABLE field is write-protected until the next reset

6.3.2 SIM Reset Status Register (SIM_RSTAT)

This register is updated upon any system reset and indicates the cause of the most recent reset. It also controls whether the COP reset vector or regular reset vector in the vector table is used. This register is asynchronously reset during Power-On Reset (see power supervisor module) and subsequently is synchronously updated based on the level of the external reset, software reset, or cop reset inputs. Only one source will ever be indicated. In the event that multiple reset sources assert simultaneously, the highest-precedence source will be indicated. The precedence from highest to lowest is POR, EXTR, COPR, and SWR. While POR is always set during a Power-On Reset (POR) has deasserted.

Base + \$1	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	SWR	COPR	EXTR	POR	0	0
Write											OWIX	oon	EXIX	1 OIX		
RESET	0	0	0	0	0	0	0	0	0	0					0	0

Figure 6-3 SIM Reset Status Register (SIM_RSTAT)

6.3.2.1 Reserved—Bits 15–6

This bit field is reserved or not implemented. It is read as zero and cannot be modified by writing.

6.3.2.2 Software Reset (SWR)—Bit 5

When set, this bit indicates that the previous system reset occurred as a result of a software reset (written 1 to SW RST bit in the SIM_CTRL register). It will not be set if a COP, external, or POR reset also occurred.

6.3.2.3 COP Reset (COPR)—Bit 4

When set, this bit indicates that the previous system reset was caused by the Computer Operating Properly (COP) timer. It will not be set if an external or POR reset also occurred. If COPR is set as code starts executing, the COP reset vector in the vector table will be used. Otherwise, the normal reset vector is used.

6.3.2.4 External Reset (EXTR)—Bit 3

When set, this bit indicates that the previous system reset was caused by an external reset. It will only be set if the external reset pin was asserted or remained asserted after the Power-On Reset deasserted.

6.3.2.5 Power-On Reset (POR)—Bit 2

This bit is set during a Power-On Reset.

6.3.2.6 Reserved—Bits 1–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.3 SIM Software Control Registers (SIM_SWC0, SIM_SWC1, SIM_SWC2, and SIM_SWC3)

Only SIM_SWC0 is shown in this section. SIM_SWC1, SIM_SWC2, and SIM_SWC3 are identical in functionality.

											T					
Base + \$2	15	14	13	12	11	10	9	8	7.	6	5	4	3	2	1	0
Read							Softw	are Con	trol Data	0 🦱	0					
Write		Software Control Data 0														
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-4 SIM Software Control Register 0 (SIM_SWC0)

6.3.3.1 Software Control Data 0 (FIELD)—Bits 15–0

This register is reset only by the Power-On Reset (POR). It has no part-specific functionality and is intended for use by a software developer to contain data that will be unaffected by the other reset sources (RESET pin, software reset, and COP reset).

6.3.4 Most Significant Half of JTAG ID (SIM_MSHID)

This read-only register displays the most significant half of the JTAG ID for the chip. This register reads \$01F2.

Base + \$6	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	1	1	1	1	1	0	0	1	0
Write																
RESET	0	0	0	0	0	0	0	1	1	1	1	1	0	0	1	0

Figure 6-5 Most Significant Half of JTAG ID (SIM_MSHID)

6.3.5 Least Significant Half of JTAG ID (SIM_LSHID)

This read-only register displays the least significant half of the JTAG ID for the chip. This register reads \$401D.

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Base + \$7	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1
Write																
RESET	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1

Figure 6-6 Least Significant Half of JTAG ID (SIM_LSHID)

6.3.6 SIM Power Control Register (SIM_PWR)

This register controls the Standby mode of the large regulator. The large regulator derives the core digital logic power supply from the IO power supply. In some circumstances, the large regulator may be put in a reduced-power Standby mode without interfering with part operation. Refer to the overview of power-down modes and the overview of clock generation for more information on the use of large regulator standby.

											A					
Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	0	0	0	LRS	TDBY
Write								-	x 12		V				Ento	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-7 SIM Power Control Register (SIM_PWR)

6.3.6.1 Reserved—Bits 15-2

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.6.2 Large Regulator Standby Mode[1:0] (LRSTDBY)—Bits 1–0

This bit controls the pull-up resistors on the IRQA pin.

- 00 = Large regulator is in Normal mode
- 01 = Large regulator is in Standby (reduced-power) mode
- 10 = Large regulator is in Normal mode and the LRSTDBY field is write-protected until the next reset
- 11 = Large regulator is in Standby mode and the LRSTDBY field is write-protected until the next reset

6.3.7 CLKO Select Register (SIM_CLKOUT)

The CLKO select register can be used to multiplex out selected clocks generated inside the clock generation and SIM modules. All functionality is for test purposes only and is subject to unspecified latencies. Glitches may be produced when the clock is enabled or switched.

The lower four bits of the GPIO A register can function as GPIO, PWM, or as additional clock output signals. GPIO has priority and is enabled/disabled via the GPIOA_PEREN. If GPIOA[3:0] are programmed to operate as peripheral outputs, then the choice between PWM and additional clock outputs is done here in the CLKOUT. The default state is for the peripheral function of GPIOA[3:0] to be programmed as PWM. This can be changed by altering PWM3 through PWM0.

Base + \$A	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Read	0	0	0	0	0	0	PWM	PWM	PWM1	PWM0	CLK		C	LKOSE	1		
Write							3	2		1 11110	DIS	CEROSEE					
RESET	0	0	0	0	0	0	0	0	0	0	1	0 0 0 0 0				0	

Figure 6-8 CLKO Select Register (SIM_CLKOUT)

6.3.7.1 Reserved—Bits 15–10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.7.2 **PWM3**—Bit 9

- $0 = Peripheral output function of GPIOA[3] is defined to be <math>\overline{PWM3}$
- 1 = Peripheral output function of GPIOA[3] is defined to be the Relaxation Oscillator Clock

6.3.7.3 PWM2—Bit 8

- 0 = Peripheral output function of GPIOA[2] is defined to be $\overline{PWM2}$
- 1 = Peripheral output function of GPIOA[2] is defined to be the system clock

6.3.7.4 PWM1—Bit 7

- $0 = Peripheral output function of GPIOA[1] is defined to be <math>\overline{PWM1}$
- 1 = Peripheral output function of GPIOA[1] is defined to be two times the rate of the system clock

6.3.7.5 PWM0—Bit 6

- $0 = Peripheral output function of GPIOA[0] is defined to be <math>\overline{PWM0}$
- 1 = Peripheral output function of GPIOA[0] is defined to be three times the rate of the system clock

6.3.7.6 Clockout Disable (CLKDIS)—Bit 5

- 0 = CLKOUT output is enabled and will output the signal indicated by CLKOSEL
- 1 = CLKOUT is 0

6.3.7.7 Clockout Select (CLKOSEL)—Bits 4–0

Selects clock to be muxed out on the CLKO pin.

- 00000 = Reserved for factory test—Continuous system clock
- 01001 = Reserved for factory test—OCCS MSTR OSC clock
- 01011 = Reserved for factory test—ADC clock
- 01100 = Reserved for factory test—JTAG TCLK
- 01101 = Reserved for factory test—Continuous peripheral clock
- 01110 = Reserved for factory test—Continuous inverted peripheral clock
- 01111 = Reserved for factory test—Continuous high-speed peripheral clock

6.3.8 SIM GPIO Peripheral Select Register (SIM_GPS)

All of the peripheral pins on the 56F8014 share their Input/Output (I/O) with GPIO ports. In order to select peripheral or GPIO control, program the GPIOx_PEREN register. In some cases, there are two possible peripherals as well as the GPIO functionality available for control of the I/O. In these cases, the SIM_GPS register is used to determine which peripheral has control.

As shown in **Figure 6-9**, the GPIO Peripheral Enable Register (PEREN) has the final control over which pin controls the I/O. SIM_GPS simply decides which peripheral will be routed to the I/O when PEREN = 1.

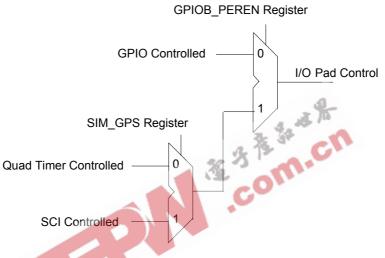


Figure 6-9 Overall Control of Pads Using SIM_GPS Control

Base + \$B	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	TCR	PCR	0	0	CFG_	CEG	6_A5	CEG	6_A4							
Write	TOIL	1 OIX			B7	B6	B5	B4	B3	B2	B1	B0	010		010	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

6.3.8.1 TMR Clock Rate (TCR)—Bit 15

This bit selects the clock speed for the TMR module.

- 0 = TMR module clock rate equals core clock rate, typically 32MHz (default)
- 1 = TMR module clock rate equals three times core clock rate
- Note: This bit should only be changed while the TMR module's clock is disabled. See Section 6.3.9.

Note: High-speed clocking is only available when the PLL is being used.

Note: If the PWM reload pulse is used as input to Timer 3 (See SIM_CTRL: TC3_INP, Section 6.3.1.7), then the clocks of the Quad Timer and PWM must be related, as shown in Table 6-2.

6.3.8.2 PWM Clock Rate (PCR)—Bit 14

This bit selects the clock speed for the PWM module.

- 0 = PWM module clock rate equals core clock rate, typically 32MHz (default)
- 1 = PWM module clock rate equals three times core clock rate

Note: This bit should only be changed while the PWM module's clock is disabled. See Section 6.3.9.

Note: High-speed clocking is only available when the PLL is being used.

Note: If the PWM reload pulse is used as input to Timer 3 (See SIM_CTRL: TC3_INP, Section 6.3.1.7), then the clocks of the Quad Timer and PWM must be related, as shown in Table 6-2.

Table 6-2 Allowable Quad Timer and PWM Clock Rates when Using PWM Reload Pulse

		Quad [•]	Timer
	Clock Speed	1X	3X
PWM	1X	OK	ОК
	3X	NO	ОК

6.3.8.3 Reserved—Bits 13–12

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

Note: Take care when programming the following CFG_* signals so as not to connect two different I/O pads to the same peripheral input. For example, do not set CFG_B7 to select SCL and also set CFG_B0 to select SCL. If this occurs for an output signal, then the signal will be routed to two I/O pads. For input signals, the values on the two I/O pads will be ORed together before reaching the peripheral.

6.3.8.4 Configure GPIOB7 (CFG_B7)—Bit 11

This bit selects the alternate function for GPIOB7.

- 0 = TXD (default)
- 1 = SCL

6.3.8.5 Configure GPIOB6 (CFG_B6)—Bit 10

This bit selects the alternate function for GPIOB6.

- 0 = RXD (default)
- 1 = SDA
- **Note:** The CLKMODE bit in the OCCS Oscillator Control register can enable this pin as the source clock to the chip. In this mode, make sure that no on-chip peripheral (including the GPIO) is driving this pin.

6.3.8.6 Configure GPIOB5 (CFG B5)—Bit 9

This bit selects the alternate function for GPIOB5.

- 0 = T1 (default)
- 1 = FAULT3

6.3.8.7 Configure GPIOB4 (CFG B4)—Bit 8

This bit selects the alternate function for GPIOB4.

- 0 = T0 (default)
- 1 = CLKO

6.3.8.8 Configure GPIOB3 (CFG B3)—Bit 7

This bit selects the alternate function for GPIOB3.

- 0 = MOSI (default)
- 1 = T3

·S ·S ·S · CN 6.3.8.9 Configure GPIOB2 (CFG B2)—Bit 6

This bit selects the alternate function for GPIOB2.

- 0 = MISO (default)
- 1 = T2

6.3.8.10 Configure GPIOB1 (CFG B1)—Bit 5

This bit selects the alternate function for GPIOB1.

- $0 = \overline{SS}$ (default)
- 1 = SDA

6.3.8.11 Configure GPIOB0 (CFG B0)—Bit 4

This bit selects the alternate function for GPIOB0.

- 0 = SCLK (default)
- 1 = SCL

6.3.8.12 Configure GPIOA5[1:0] (CFG A5)—Bits 3–2

These bits select the alternate function for GPIOA5.

- 00 = Select PWM5 when peripheral mode is enabled in GPIOA5 (default)
- 01 = Select PWM5 when peripheral mode is enabled in GPIOA5
- 10 = Select FAULT2 when peripheral mode is enabled in GPIOA5
- 11 = Select T3 when peripheral mode is enabled in GPIOA5 ٠

6.3.8.13 Configure GPIOA4[1:0] (CFG_A4)—Bits 1–0

These bits select the alternate function for GPIOA4.

- 00 = Select PWM4 when peripheral mode is enabled in GPIOA4 (default)
- 01 = Select PWM4 when peripheral mode is enabled in GPIOA4
- 10 = Select FAULT1 when peripheral mode is enabled in GPIOA4
- 11 = Select T2 when peripheral mode is enabled in GPIOA4

6.3.9 Peripheral Clock Enable Register (SIM_PCE)

The Peripheral Clock Enable register is used to enable or disable clocks to the peripherals as a power savings feature. The clocks can be individually controlled for each peripheral on the chip. The corresponding peripheral should itself be disabled while its clock is shut off. IPBus writes cannot be made to a module that has its clock disabled.

Base + \$C	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	I2C	0	ADC	0	0	0	0	0	0	TMR		SCI	0	SPI	0	PWM
Write	120		NB0							4	a m	001		011		1 00101
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-11 Peripheral Clock Enable Register (SIM_PCE)

6.3.9.1 I²C IPBus Clock Enable (I2C)-Bit 15

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled)
- 1 = Clocks are enabled

6.3.9.2 Reserved-Bit 14

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.9.3 Analog-to-Digital Converter IPBus Clock Enable (ADC)—Bit 13

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled)
- 1 = Clocks are enabled

6.3.9.4 Reserved—Bits 12–7

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.9.5 Timer IPBus Clock Enable (TMR)—Bit 6

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled)
- 1 = Clocks are enabled

6.3.9.6 Reserved—Bit 5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.9.7 SCI IPBus Clock Enable (SCI)—Bit 4

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled)
- 1 =Clocks are enabled

6.3.9.8 Reserved—Bit 3

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.9.9 SPI IPBus Clock Enable (SPI)—Bit 2

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled) 78 34 × 18
- 1 = Clocks are enabled

6.3.9.10 Reserved—Bit 1

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

PWM IPBus Clock Enable (PWM)—Bit 0 6.3.9.11

Each bit controls clocks to the indicated peripheral.

- 0 = The clock is not provided to the peripheral (the peripheral is disabled) •
- 1 = Clocks are enabled

6.3.10 I/O Short Address Location Register (SIM IOSAHI and SIM IOSALO)

The I/O Short Address Location registers are used to specify the memory referenced via the I/O short address mode. The I/O short address mode allows the instruction to specify the lower six bits of address; the upper address bits are not directly controllable. This register set allows limited control of the full address, as shown in Figure 6-12.

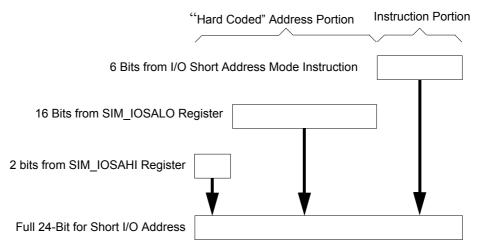


Figure 6-12 I/O Short Address Determination

With this register set, an interrupt driver can set the SIM_IOSALO register pair to point to its peripheral registers and then use the I/O Short addressing mode to reference them. The ISR should restore this register to its previous contents prior to returning from interrupt.

Note: The default value of this register set points to the EOnCE registers.

Note: The pipeline delay between setting this register set and using short I/O addressing with the new value is five instruction cycles.

Base + \$D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	0	0	0	ISAL	23:22]
Write															.0, .1	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1

Figure 6-13 I/O Short Address Location High Register (SIM_IOSAHI)

6.3.10.1 Reserved—Bits 15—2

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.3.10.2 Input/Output Short Address Location (ISAL[23:22])—Bit 1–0

This field represents the upper two address bits of the "hard coded" I/O short address.

Base + \$E	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read		ISAL[21:6]														
Write		ISAL[21:6]														
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 6-14 I/O Short Address Location Low Register (SIM_IOSALO)

6.3.10.3 Input/Output Short Address Location (ISAL[21:6])—Bit 15–0

This field represents the lower 16 address bits of the "hard coded" I/O short address.

6.4 Clock Generation Overview

The SIM uses master clocks from the OCCS module to produce the peripheral and system (core and memory) clocks. The HS_PERF clock input from OCCS operates at three times the system and peripheral bus rate, or a maximum of 96MHz. The SYS_CLK_x2 clock input from OCCS operates at two times the system and peripheral bus rate, or a maximum of 64MHz. Peripheral and system clocks are generated at a maximum of 32MHz by dividing the SYS_CLK_x2 clock by two and gating it with appropriate power mode and clock gating controls. The PWM and TIMER peripheral clocks can optionally be generated at three times the normal rate at a maximum 96MHz. These clocks are generated by gating the HS_PERF clock with appropriate power mode and clock gating controls.

The OCCS configuration controls the operating frequency of the SIM's master clocks. In the OCCS, either an external clock or the relaxation oscillator can be selected as the master clock source (MSTR_OSC). When selected, the relaxation oscillator can be operated at full speed (8MHz), standby speed (400kHz using ROSB), or powered down (using ROPD). An 8MHz MSTR_OSC can be multiplied to 196MHz using the PLL and postscaled to provide a variety of high speed clock rates. Either the postscaled PLL output or MSTR_OSC signal can be selected to produce the master clocks to the SIM. When the PLL is not selected, the HS_PERF clock is disabled and the SYS_CLK_x2 clock is MSTR_OSC.

In combination with the OCCS module, the SIM provides power modes (see Section 6.5), clock enables (SIM_PCE register, CLK_DIS, ONCE_EBL), and clock rate controls (TCR, PCR) to provide flexible control of clocking and power utilization. The SIM's clock enable controls can be used to disable individual clocks when not needed. The clock rate controls enable the high speed clocking option for the Timer channels and PWM but require the PLL to be on and selected. Refer to the **56F801X Peripheral Reference Manual** for further details.

6.5 Power-Down Modes

The 56F8014 operates in one of five Power-Down modes, as shown in Table 6-3.

Mode	Core Clocks	Peripheral Clocks	Description
Run	Core and memory clocks disabled	Peripheral clocks enabled	Device is fully functional
Wait	Core and memory clocks disabled	Peripheral clocks enabled	Core executes WAIT instruction to enter this mode. Typically used for power-conscious applications. Possible recoveries from Wait mode to Run mode are: 1. Any interrupt 2. Executing a Debug mode entry command during the 56800E core JTAG interface 2. Any reset (POR, external, software, COP)
Stop	Master clock genera remains operational, the generation of sys clocks.	but the SIM disables	Core executes STOP instruction to enter this mode. Possible recoveries from Stop mode to Run mode are: 1. Interrupt from TMR channels that have been configured to operate in Stop mode (TCx_SD) 2. Interrupt for SCI configured to operate in Stop mode (SCI_SD) 3. Low-voltage interrupt 4. Executing a Debug mode entry command using the 56800E core JTAG interface 5. Any reset (POR, external, software, COP)
Standby		equency (400kHz). The clocks are disabled and heral option is not	The user configures the OCCS and SIM to select the relaxation oscillator clock source (PRECS), shut down the PLL (PLLPD), put the relaxation oscillator in Standby mode (ROSB), and put the large regulator in Standby (LRSTDBY). The part is fully operational, but operating at a minimum frequency and power configuration. Recovery requires reversing the sequence used to enter this mode (allowing for PLL lock time).
Power-Down	Master clock genera completely shut dow peripheral clocks are	n. All system and	The user configures the OCCS and SIM to enter Standby mode as shown in the previous description, followed by powering down the oscillator (ROPD). The only possible recoveries from this mode are: 1. External reset 2. Power-on reset

Table 6-3 Clock Operation in Power-Down Modes

The power modes provide additional means to disable clock domains, configure the voltage regulator, and configure clock generation to manage power utilization, as shown in **Table 6-3**. Run, Wait, and Stop modes provide means of enabling/disabling the peripheral and/or core clocking as a group. Stop disable controls are provided for selected peripherals in the control register (SCI and TMR channels) so that these peripheral clocks can optionally continue to operate in Stop mode and generate interrupts which will return the part from Stop to Run mode. Standby mode provides normal operation but at very low speed and power utilization. It is possible to invoke Stop or Wait mode while in Standby mode for even greater levels of power reduction. A 400kHz clock external clock can optionally be used in Standby mode to produce the

required Standby 200kHz system bus rate. Power-down mode, which selects the ROSC clock source but shuts it off, fully disables the part and minimizes its power utilization but is only recoverable via reset.

When the PLL is not selected and the system bus is operating at 200kHz or less, the large regulator can be put into its Standby mode (LRSTDBY) to reduce the power utilization of that regulator.

All peripherals, except the COP/watchdog timer, run at the IPBus clock (peripheral bus) frequency¹, which is the same as the main processor frequency in this architecture. The COP timer runs at MSTR_OSC / 1024. The maximum frequency of operation is SYS_CLK = 32MHz. The only exception is the TMR and PWM, which can be configured to operate at three times the system bus rate using TCR and PCR controls, provided the PLL is active and selected.

6.6 Resets

The SIM supports four sources of reset, as shown in **Figure 6-15**. The two asynchronous sources are the external reset pin and the Power-On Reset (POR). The two synchronous sources are the software reset, which is generated within the SIM itself by writing the SIM_CTRL register in Section 6.3.1, and the COP reset. The SIM uses these to generate resets for the internal logic. These are outlined in Table 6-4. The first column lists the four primary resets which are calculated. The JTAG circuitry is reset by the Power-On Reset. Columns two through five indicate which reset sources trigger these reset signals. The last column provides additional detail.

		Reset S	Sources		
Reset Signal	POR	External	Software	СОР	Comments
EXTENDED_POR	x				Stretched version of POR. Relevant 64 Relaxation Oscillator Clock cycles after POR deasserts.
CLKGEN_RST	х	х	Х	Х	Released 32 Relaxation Oscillator Clock cycles after all reset sources have released.
PERIP_RST	Х	Х	Х	х	Releases 32 Relaxation Oscillator Clock cycles after the CLKGEN_RST is released.
CORE_RST	Х	Х	Х	Х	Releases <u>32</u> SYS_CLK periods after PERIP_RST is released.

Table 6-4 Primary System Resets

Figure 6-15 provides a graphic illustration of the details in **Table 6-4**. Note that the POR_Delay blocks use the Relaxation Oscillator Clock as their time base since other system clocks are inactive during this phase of reset.

^{1.} The TMR ans PWM modules can be operated at three times the IPBus clock frequency.

Resets

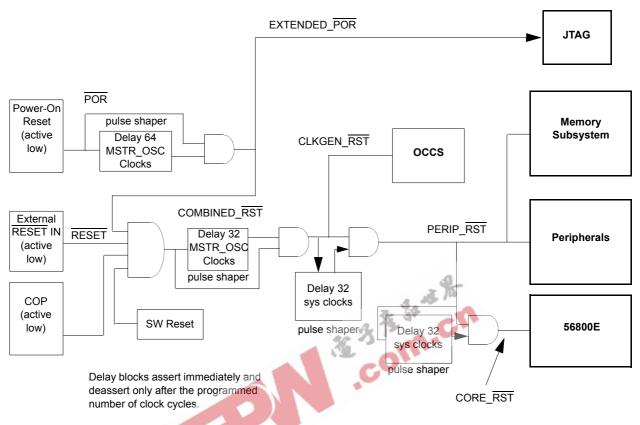


Figure 6-15 Sources of RESET Functional Diagram (Test modes not included)

POR resets are extended 64 MSTR_OSC clocks to stabilize the power supply. All resets are subsequently extended for an additional 32 MSTR_OSC clocks and 64 system clocks as the various internal reset controls are released. Given the normal relaxation oscillator rate of 8MHz, the duration of a POR reset from when power comes on to when code is running is 28μ S. An external reset generation chip may also be used. Resets may be asserted asynchronously, but they are always released internally on a rising edge of the system clock.

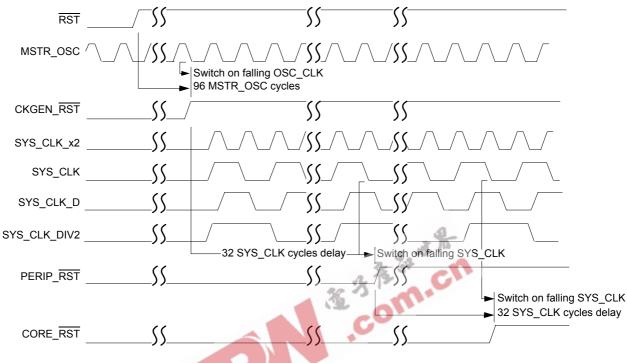
6.7 Clocks

The memory, peripheral and core clocks all operate at the same frequency (32MHz max) with the exception of the TMR and PWM peripheral clocks, which have the option (using TCR and PCR) to operate three times faster. The SIM is responsible for stalling individual clocks as a response to various hold-off requests, low power modes, and other configuration parameters. The SIM has access to the following signals from the OCCS module:

- MSTR_OSC This comes from the input clock source mux of the OCCS. It is the output of the relaxation oscillator or the external clock source, depending on PRECS. It is not guaranteed to be at 50% duty cycle (+ or 10% can probably be assumed for design purposes). This clock runs continuously, even during reset and is used for reset generation.
- HS_PERF The PLL multiplies the MSTR_OSC by 24, to a maximum of 192MHz. The ZSRC field in OCCS selects the active source to be the PLL. This is divided by 2 and postscaled to produce this maximum 96MHz clock. It is used without further division to produce the high-speed (3x system bus rate) variants of the TMR and PWM peripheral clocks. This clock is disabled when ZSRC is selecting MSTR_OSC.
- SYS_CLK_x2 The PLL can multiply the MSTR_OSC by 24, to a maximum of 192MHz. When the PLL is selected by the OCCS ZSRC field, the PLL is divided by three and postscaled to produce this maximum 64MHz clock. When MSTR_OSC is selected by the OCCS ZSRC field, MSTR_OSC feeds SYS_CLK_x2 directly. The SIM takes this clock and divides it by two to generate all the normal (1x system bus rate) peripheral and system clocks.

While the SIM generates the ADC peripheral clock in the same way it generates all other peripheral clocks, the ADC standby and conversion clocks are generated by a direct interface between the ADC and the OCCS module.

Figure 6-16 illustrates clock relationships to one another and to the various resets as the device comes out of reset. RST is assumed to be the logical AND of all active-low system resets (for example, POR, external reset, COP and Software reset). In the 56F8014 architecture, this signal will be stretched by the SIM for a period of time (up to 96 MSTR_OSC clock cycles, depending upon the status of the POR) to create the clock generation reset signal (CLKGEN_RST). The SIM should deassert CLKGEN_RST synchronously with the negative edge of OSC_CLK in order to avoid skew problems. CLKGEN_RST is delayed 32 SYS_CLK cycles to create the peripheral reset signal (PERIP_RST). PERIP_RST is then delayed by 32 SYS_CLK cycles to create CORE_RST. Both PERIP_RST and CORE_RST should be released on the negative edge of SYS_CLK_D as shown. This phased releasing of system resets is necessary to give some peripherals (for example, the Flash interface unit) set-up time prior to the 56800E core becoming active.



Maximum Delay = 64 MSTR_OSC cycles for POR reset extension and 32 MSTR_OSC cycles for combined reset extension

Figure 6-16 Timing Relationships of Reset Signal to Clocks

6.8 Interrupts

The SIM generates no interrupts.

Part 7 Security Features

The 56F8014 offers security features intended to prevent unauthorized users from reading the contents of the Flash Memory (FM) array. The 56F8014's Flash security consists of several hardware interlocks that prevent unauthorized users from gaining access to the Flash array.

Note, however, that part of the security must lie with the user's code. An extreme example would be user's code that includes a subroutine to read and transfer the contents of the internal program to SCI, SPI or another peripheral, as this code would defeat the purpose of security. At the same time, the user may also wish to put a "backdoor" in his program. As an example, the user downloads a security key through the SCI, allowing access to a programming routine that updates parameters stored in another section of the Flash.

7.1 **Operation with Security Enabled**

Once the user has programmed the Flash with his application code, the 56F8014 can be secured by programming the security bytes located in the FM configuration field, which are located at the last 9 words of Program Flash. These non-volatile bytes will keep the part secured through reset and through power-down of the device. Only two bytes within this field are used to enable or disable security. Refer to the Flash Memory chapter in the 56F801X Peripheral Reference Manual for the state of the security bytes and the resulting state of security. When Flash security mode is enabled in accordance with the method described in the Flash Memory module chapter, the 56F8014 will disable the core EOnCE debug capabilities. Normal program execution is otherwise unaffected.

7.2 Flash Access Lock and Unlock Mechanisms

The 56F8014 has several operating functional and debug modes. Effective Flash security must address operating mode selection and anticipate modes in which the on-chip Flash can be read without explicit user permission.

7.2.1 **Disabling EOnCE Access**

2. 2 % On-chip Flash can be read by issuing commands across the EOnCE port, which is the debug interface for the 56800E CPU. The TCLK, TMS, TDO, and TDI pins comprise a JTAG interface onto which the EOnCE port functionality is mapped. When the 56F8014 boots, the chip-level JTAG TAP (Test Access Port) is active and provides the chip's boundary scan capability and access to the ID register, but proper implementation of Flash security will block any attempt to access the internal Flash memory via the EOnCE port when security is enabled.

7.2.2 Flash Lockout Recovery Using JTAG

If a user inadvertently enables security on the 56F8014, the only lockout recovery mechanism is the complete erasure of the internal Flash contents, including the configuration field, and thus disables security (the protection register is cleared). This does not compromise security, as the entire contents of the user's secured code stored in Flash are erased before security is disabled on the 56F8014 on the next reset or power-up sequence.

To start the lockout recovery sequence, the JTAG public instruction (LOCKOUT RECOVERY) must be shifted into the chip-level TAP controller's instruction register. Once first the LOCKOUT RECOVERY instruction has been shifted into the instruction register, the clock divider value must be shifted into the corresponding 7-bit data register. After the data register has been updated, the user must transition the TAP controller into the RUN-TEST/IDLE state for the lockout sequence to commence. The controller must remain in this state until the erase sequence has completed. Refer to the 56F801X Peripheral Reference Manual for more details, or contact Freescale.

Once the lockout recovery sequence has completed, the user must reset both the JTAG TAP controller Note: (by advancing the TAP state machine to the reset state) and the 56F8014 (by asserting external chip reset) to return to normal unsecured operation.

7.2.3 Flash Lockout Recovery using CodeWarrior

CodeWarrior can unlock a device using the command sequence described in Section 7.2.2 by selecting the *Debug* menu, then selecting *DSP56800E*, followed by *Unlock Flash*.

Another mechanism is also built into CodeWarrior using the device's memory configuration file. The command "Unlock_Flash_on_Connect1" in the .cfg file accomplishes the same task as using the Debug menu.

7.2.4 Product Analysis

The recommended method of unsecuring a programmed 56F8014 for product analysis of field failures is via the backdoor key access. The customer would need to supply Technical Support with the backdoor key and the protocol to access the backdoor routine in the Flash. Additionally, the KEYEN bit that allows backdoor key access must be set.

An alternative method for performing analysis on a secured microcontroller would be to mass-erase and reprogram the Flash with the original code, but modify the security bytes.

To insure that a customer does not inadvertently lock himself out of the 56F8014 during programming, it is recommended that the user program the backdoor access key first, the application code second and the security bytes within the FM configuration field last.

Part 8 General Purpose Input/Output (GPIO)

8.1 Introduction

This section is intended to supplement the GPIO information found in the **56F801X Peripheral Reference Manual** and contains only chip-specific information. This information supercedes the generic information in the **56F801X Peripheral Reference Manual**.

8.2 Configuration

There are four GPIO ports defined on the 56F8014. The width of each port, the associated peripheral and reset functions are shown in **Table 8-1**. The specific mapping of GPIO port pins is shown in **Table 8-2**.

GPIO Port	Available Pins in 56F8014	Peripheral Function	Reset Function
А	6	PWM, Reset	GPIO, except GPIOA7
В	8	SPI, SCI, Timer	GPIO
С	8	ADC	Analog
D	4	JTAG	JTAG

Table 8-1 GPIO Ports Configuration

GPIO Function	Peripheral Function	LQFP Package Pin	Notes
GPIOA0	PWM0	28	Defaults to A0
GPIOA1	PWM1	27	Defaults toA1
GPIOA2	PWM2	23	Defaults to A2
GPIOA3	PWM3		Not bonded out in 56F8014 Defaults to A3
GPIOA4	PWM4 / FAULT1 / T2	22	SIM register SIM_GPS is used to select between PWM4, FAULT1, and T2 Defaults to A4
GPIOA5	PWM5 / FAULT2 / T3	20	SIM register SIM_GPS is used to select between PWM5, FAULT2, and T3 Defaults to A5
GPIOA6	FAULT0	CC CC	Not bonded out in 56F8014 Defaults to A6
GPIOA7	RESET	16	Defaults to RESET
GPIOB0	SCLK / SCL	21	SIM register SIM_GPS is used to select between SCLK and SCL Defaults to B0
GPIOB1	SS / SDA	1	SIM register SIM_GPS is used to select between SS and SDA Defaults to B1
GPIOB2	MISO / T2	18	SIM register SIM_GPS is used to select between MISO and T2 Defaults to B2
GPIOB3	MOSI / T3	17	SIM register SIM_GPS is used to select between MOSI and T3 Defaults to B3
GPIOB4	T0 / CLKO	19	SIM register SIM_GPS is used to select between T0 and CLKO Defaults to B4
GPIOB5	T1 / FAULT3	3	SIM register SIM_GPS is used to select between T1 and FAULT3 Defaults to B5

Table 8-2 GPIO External Signals MapPins in shaded rows are not available in 56F8014

GPIO Function	Peripheral Function	LQFP Package Pin	Notes
GPIOB6	RXD / SDA / CLKIN	32	SIM register SIM_GPS is used to select between RXD and SDA. CLKIN functionality is enabled using the PLL Control Register within the OCCS block. Defaults to B6
GPIOB7	TXD / SCL	2	SIM register SIM_GPS is used to select between TXD and SCL Defaults to B7
GPIOC0	ANA0	13	Defaults to ANA0
GPIOC1	ANA1	12	Defaults to ANA1
GPIOC2	ANA2 / V _{REFH}	11	Defaults to ANA2
GPIOC3	ANA3	10	Defaults to ANA3
GPIOC4	ANB0	4 3	Defaults to ANB0
GPIOC5	ANB1	5	Defaults to ANB1
GPIOC6	ANB2 / V _{REFL}	6	Defaults to ANB2
GPIOC7	ANB3	7	Defaults to ANB3
GPIOD0	TDI	29	Defaults to TDI
GPIOD1	TDO	31	Defaults to TDO
GPIOD2	тск	15	Defaults to TCK
GPIOD3	TMS	30	Defaults to TMS

Table 8-2 GPIO External Signals Map (Continued)Pins in shaded rows are not available in 56F8014

8.3 Reset Values

Tables 4-16 through 4-19 detail registers for the 56F8014; Figures 8-1 through 8-4 summarize register maps and reset values.

Add. Offset	Register Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	GPIOA_PUPEN	R W RS	0	0	0	0	0	0	0	0	1	1	1	P 1	U	1	1	1
\$1	GPIOA_DATA	R	0	0	0	0	0	0	0	0	1	1	1	, [)			-
φı	GFIOA_DATA	RS	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
\$2	GPIOA_DDIR	R W RS	0	0	0	0	0	0	0	0	0	0	0	D 0	D 0	0	0	0
\$3	GPIOA_PEREN	R W RS	0	0	0	0	0	0	0	0	1	0	0	P 0	E 0	0	0	0
\$4	GPIOA_IASSRT	R W	0	0	0	0	0	0	0	0	4.0 ×	S. A		l,	Ą			
		RS R	0	0	0	0	0	0		0	0	0	0	0	0	0	0	0
\$5	GPIOA_IEN	W RS	0	0	0	0	0	0	0	P	0	0	0	IE 0	N 0	0	0	0
\$6	GPIOA_IEPOL	R W RS	0	0	0		0	0	0	0	0	0	0	IEP 0	POL 0	0	0	0
\$7	GPIOA_IPEND	R W RS	0	0	0	0	0	0	0	0	0	0	0	IP 0	R 0	0	0	0
\$8	GPIOA_IEDGE	R W RS	0	0	0	0	0	0	0	0	0	0	0	IE 0	S 0	0	0	0
\$9	GPIOA_PPOUTM	R W RS	0	0	0	0	0	0	0	0	1	1	1	OE 1		1	1	1
\$A	GPIOA_RDATA	R W RS	0 X	0 X	0 X	0 X	0 X	0 X	0 X	0 X	X	X	X	RAW X	DATA X	X	X	X
\$B	GPIOA_DRIVE	R W RS	0	0	0	0	0	0	0	0	0	0	0	DR 0		0	0	0
		R W RS	0	Read Rese Reset	l as 0 rved						U	0	0	0	0			0

Figure 8-1 GPIOA Register Map Summary

Reset Values

Add. Offset	Register Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	GPIOB_PUPEN	R W RS	0	0	0	0	0	0	0	0	1	1	1	P 1	U 1	1	1	1
\$1	GPIOB_DATA	R W RS	0	0	0	0	0	0	0	0	1	1	1	1) 1	1	1	1
\$2	GPIOB_DDIR	R W RS	0	0	0	0	0	0	0	0	0	0	0	D 0	D	0	0	0
\$3	GPIOB_PEREN	R W RS	0	0	0	0	0	0	0	0	0	0	0		'E 0	0	0	0
\$4	GPIOB_IASSRT	R W	0	0	0	0	0	0	0	0	4.0 ×	S. A		l,	A			
\$5	GPIOB_IEN	RS R W	0	0	0	0	0	0	0	0	<u> </u>	0	0	0 IE	0 EN	0	0	0
\$6	GPIOB_IEPOL	RS R W	0	0	0	0	0	0	0	0	0	0	0	0 IEF	0 POL	0	0	0
φυ		RS	0	0	0	0	0	0	0	0	0	0	0	0	0 PR	0	0	0
\$7	GPIOB_IPEND	RS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
\$8	GPIOB_IEDGE	R W RS	0	0	0	0	0	0	0	0	0	0	0	IE 0	S 0	0	0	0
\$9	GPIOB_PPOUTM	R W RS	0	0	0	0	0	0	0	0	1	1	1	0E 1	EN 1	1	1	1
\$A	GPIOB_RDATA	R W RS	0 X	0 X	0 X	0 X	0 X	0 X	0 X	0 X	X	X	X	RAW X	DATA X	X	X	X
\$B	GPIOB_DRIVE	R W RS	0	0	0	0	0	0	0	0	0	0	0	DR 0	IVE 0	0	0	0
		R W RS	0	Reac Rese Reset	l as 0 erved						<u> </u>							

Figure 8-2 GPIOB Register Map Summary

Add. Offset	Register Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	GPIOC_PUPEN	R W RS	0	0	0	0	0	0	0	0	1	1	1	P		1	1	1
\$1	GPIOC_DATA	R	0	0	0	0	0	0	0	0	1	1	1		, ' ,			
φī	GFIOC_DATA	RS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
\$2	GPIOC_DDIR	R W RS	0	0	0	0	0	0	0	0	0	0	0	D 0	0 0	0	0	0
\$3	GPIOC_PEREN	R W RS	0	0	0	0	0	0	0	0	1	1	1	P	PE	1	1	1
\$4	GPIOC_IASSRT	R W RS	0	0	0	0	0	0	0	0	0	A A	0	ا ا	A 0	0	0	0
\$5	GPIOC_IEN	R W	0	0	0	0	0	0		0	Ŵ	2		IE	ĒN			
		RS R	0	0	0		0		0	0	0	0	0	0	0	0	0	0
\$6	GPIOC_IEPOL	W RS	0	0	0	0	0	0	0	0	0	0	0	IEF 0	POL 0	0	0	0
\$7	GPIOC_IPEND	R W RS	0	0	0	0	0	0	0	0	0	0	0	IF 0	PR 0	0	0	0
\$8	GPIOC_IEDGE	R W RS	0	0	0	0	0	0	0	0	0	0	0	IE 0	ES	0	0	0
\$9	GPIOC_PPOUTM	R W RS	0	0	0	0	0	0	0	0	1	1	1		EN			
\$A		R	0	0	0	0	0	0	0	0					DATA			
	GPIOC_RDATA		24	24			T T	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х
		RS R	X 0	X 0	X 0	X 0	X 0	0	0	0				DR	IVE	^		
\$B	GPIOC_RDATA	RS			0						0	0	0	DR 0	I	0	0	0

Figure 8-3 GPIOC Register Map Summary

Reset Values

Add. Offset	Register Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3 2 1 0
\$0	GPIOD_PUPEN	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	PU 1 1 1 1
\$1	GPIOD_DATA	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	D 0 0 0 0
\$2	GPIOD_DDIR	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	DD 0 0 0 0
\$3	GPIOD_PEREN	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	PE
\$4	GPIOD_IASSRT	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	IA 0 0 0 0
\$5	GPIOD_IEN	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	IEN 0 0 0 0 0
\$6	GPIOD_IEPOL	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	
\$7	GPIOD_IPEND	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	IPR 0 0 0 0
\$8	GPIOD_IEDGE	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	IES
\$9	GPIOD_PPOUTM	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	OEN 1 1 1 1
\$A	GPIOD_RDATA	R W RS	0 X	RAW DATA											
\$B	GPIOD_DRIVE	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	DRIVE
		R	0	Read	as 0										

 R
 0
 Read as 0

 W
 Reserved

 RS
 Reset

Figure 8-4 GPIOD Register Map Summary

Part 9 Joint Test Action Group (JTAG)

9.1 56F8014 Information

Please contact your Freescale sales representative or authorized distributor for device/package-specific BSDL information.

The $\overline{\text{TRST}}$ pin is not available in this package. The pin is tied to V_{DD} in the package.

The JTAG state machine is reset during POR and can also be reset via a soft reset by holding TMS high for five rising edges of TCK, as described in the **56F8000 Peripheral User Manual**.

Part 10 Specifications

10.1 General Characteristics

The 56F8014 is fabricated in high-density CMOS with 5V-tolerant TTL-compatible digital inputs. The term "5V-tolerant" refers to the capability of an I/O pin, built on a 3.3V-compatible process technology, to withstand a voltage up to 5.5V without damaging the device. Many systems have a mixture of devices designed for 3.3V and 5V power supplies. In such systems, a bus may carry both 3.3V- and 5V-compatible I/O voltage levels (a standard 3.3V I/O is designed to receive a maximum voltage of $3.3V \pm 10\%$ during normal operation without causing damage). This 5V-tolerant capability therefore offers the power savings of 3.3V I/O levels, combined with the ability to receive 5V levels without damage.

Absolute maximum ratings in **Table 10-1** are stress ratings only, and functional operation at the maximum is not guaranteed. Stress beyond these ratings may affect device reliability or cause permanent damage to the device.

Unless otherwise stated, all specifications within this chapter apply over the temperature range of -40°C to 125°C ambient temperature over the following supply ranges: $V_{SS} = V_{SS}A = 0V$, $V_{DD} = V_{DDA} = 3.0-3.6V$, $CL \le 50pF$, $f_{OP} = 32MHz$

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Characteristic	Symbol	Notes	Min	Max	Unit
Supply Voltage Range	V _{DD}		-0.3	4.0	V
Analog Supply Voltage Range	V _{DDA}		- 0.3	4.0	V
ADC High Voltage Reference	V _{REFH}		- 0.3	4.0	V
Voltage difference V_{DD_IO} to V_{DDA}	ΔV_{DD}		- 0.3	0.3	V
Voltage difference V_{SS_IO} to V_{SSA}	ΔV_{SS}		- 0.3	0.3	V
Input Voltage Range (Digital inputs)	V _{IN}	Pin Groups 1, 2	- 0.3	6.0	V
Input Voltage Range (ADC inputs) ¹	V _{INA}	Pin Group 3	- 0.3	4.0	V
Input clamp current, per pin $(V_{IN} < 0)^2$	V _{IC}		g	-20	mA
Output clamp current, per pin $(V_0 < 0)^2$	V _{OC}	34 SP	-1-	-20	mA
Output Voltage Range (Normal Push-Pull mode)	V _{OUT}	Pin Group 1	-0.3	4.0	V
Output Voltage Range (Open Drain mode)	Voutod	Pin Groups 1, 2	-0.3	6.0	V
Ambient Temperature	T _A		-40	105	°C
Storage Temperature	T _{STG}		-55	150	°C

Table 10-1 Absolute Maximum Ratings (V_{SS} = 0V, V_{SSA} = 0V)

1. Pin Group 3 can tolerate 6V for less than 5 seconds when they are configured as ADC inputs or during reset. Pin Group 3 can tolerate 6V if they are configured as GPIO.

2. Continuous input current per pin is -2 mA

Default Mode

Pin Group 1: GPIO, TDI, TDO, TMS, TCK Pin Group 2: RESET, GPIOA7 Pin Group 3: ADC analog inputs

10.1.1 ElectroStatic Discharge (ESD) Model

Table 10-2 56	F8014 ES	D Protectio	on

Characteristic	Min	Тур	Max	Unit
ESD for Human Body Model (HBM)	2000	_	_	V
ESD for Machine Model (MM)	200	—	—	V
ESD for Charge Device Model (CDM)	750			V

Characteristic	Comments	Symbol	Value (LQFP)	Unit	Notes
Junction to ambient Natural convection	Single layer board (1s)	$R_{ hetaJA}$	74	°C/W	1,2
Junction to ambient Natural convection	Four layer board (2s2p)	$R_{ heta JMA}$	50	°C/W	1,3
Junction to ambient (@200 ft/min)	Single layer board (1s)	$R_{ heta JMA}$	67	°C/W	1,3
Junction to ambient (@200 ft/min)	Four layer board (2s2p)	$R_{ heta JMA}$	46	°C/W	1,3
Junction to board		$R_{ hetaJB}$	23	°C/W	4
Junction to case		$R_{ ext{ heta}JC}$	20-	°C/W	5
Junction to package top	Natural Convection	Ψ _{JT}	4	°C/W	6

Table 10-3 LQFP Package Thermal Characteristics⁶

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.

- 2. Per SEMI G38-87 and JEDEC JESD51-2 with the single layer board horizontal.
- 3. Per JEDEC JESC51-6 with the board horizontal.
- 4. Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
- 5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
- 6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.
- 7. See Section 12.1 for more details on thermal design considerations.

Table 10-4 Recommended Operating Conditions (V_{REFL} = 0V, V_{SSA} = 0V, V_{SS} = 0V)

Characteristic	Symbol	Notes	Min	Тур	Мах	Unit
Supply voltage	V _{DD}		3	3.3	3.6	V
ADC Supply voltage	V _{DDA}		3	3.3	3.6	V
ADC High Voltage Reference	V _{REFH}		3		V _{DDA}	V
Voltage difference V_{DD_IO} to V_{DDA}	ΔV_{DD}		-0.1	0	0.1	V
Voltage difference V_{SS_IO} to V_{SSA}	ΔV _{SS}		-0.1	0	0.1	V
Device Clock Frequency Using relaxation oscillator Using external clock source	FSYSCLK		8 0	_	32 32	MHz
Input Voltage High (digital inputs)	V _{IH}	Pin Groups 1, 2	2		5.5	V
Input Voltage Low (digital inputs)	V _{IL}	Pin Groups 1, 2	-0.3		0.8	V
Output Source Current High (at V _{OH} min.) When programmed for low drive strength When programmed for high drive strength	I _{ОН}	Pin Group 1 Pin Group 1	T	_	-4 -8	mA
Output Source Current Low (at V _{OL} max.) When programmed for low drive strength When programmed for high drive strength	I _{OL}	Pin Groups 1, 2 Pin Groups 1, 2	_		4 8	mA
Ambient Operating Temperature	TA		-40		105	°C
Flash Endurance (Program Erase Cycles)	N _F	T _A = -40°C to 105°C	10,000	—		Cycles
Flash Data Retention	T _R	T _J <= 85°C avg	15	_	_	Years
Flash Data Retention with <100 Program/Erase Cycles	t _{FLRET}	T _J <= 85°C avg	20	_	_	Years

Note: Total chip source or sink current cannot exceed 50mA

Default Mode

Pin Group 1: GPIO, TDI, TDO, TMS, TCK Pin Group 2: RESET, GPIOA7 Pin Group 3: ADC analog inputs

10.2 DC Electrical Characteristics

Table 10-5 DC Electrical Characteristics

At Recommended Operating	Conditions
--------------------------	------------

Characteristic	Symbol	Notes	Min	Тур	Max	Unit	Test Conditions
Output Voltage High	V _{OH}	Pin Group 1	2.4	_	_	V	I _{OH} = I _{OHmax}
Output Voltage Low	V _{OL}	Pin Groups 1, 2	_	_	0.4	V	I _{OL} = I _{OLmax}
Digital Input Current High pull-up enabled or disabled ¹	I _{IH}	Pin Groups 1, 2	_	0	+/- 2.5	μA	V _{IN} = 2.4V to 5.5V
Digital Input Current Low pull-up enabled pull-up disabled ¹	IIL	Pin Groups 1, 2	-15 —	-30 0	-60 +/- 2.5	μA	V _{IN} = 0V
Output Current High Impedance State ¹	I _{OZ}	Pin Groups 1, 2	4.	*%	+/- 2.5	μA	V _{OUT} = 2.4V to 5.5V or 0V
Schmitt Trigger Input Hysteresis	V _{HYS}	Pin Groups 1, 2	12	0.35	_	V	—
Input Capacitance	C _{IN}	32	o,	10	_	pF	_
Output Capacitance	C _{OUT}		_	10	_	pF	—
1. See Figure 10-1			•				

Default Mode

Pin Group 1: GPIO, TDI, TDO, TMS, TCK Pin Group 2: RESET, GPIOA7 Pin Group 3: ADC analog inputs

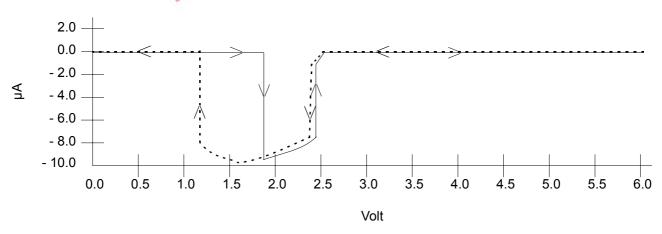


Figure 10-1 I_{IN}/I_{OZ} vs. V_{IN} (Typical; Pull-Up Disabled)

Mada	Conditions	Typical @	3.3V, 25°C	Maximum@ 3.6V, 25°C	
Mode	Conditions		I _{DDA}	I _{DD} ¹	I _{DDA}
RUN	32MHz Device Clock Relaxation Oscillator on PLL powered on Continuous MAC instructions with fetches from Program Flash All peripheral modules enabled. TMR and PWM using 1x Clock ADC powered on and clocked	42mA	13.5mA		_
WAIT	32MHz Device Clock Relaxation Oscillator on PLL powered on Processor Core in WAIT state All Peripheral modules enabled. TMR and PWM using 1x Clock ADC powered off 4MHz Device Clock	17mA	ΟμΑ		_
STOP	4MHz Device Clock Relaxation Oscillator on PLL powered off Processor Core in STOP state All peripheral module and core clocks are off ADC powered off	5mA	0μΑ		_
STANDBY > STOP	100KHz Device Clock Relaxation Oscillator in Standby mode PLL powered off Processor Core in STOP state All peripheral module and core clocks are off ADC powered off Voltage regulator in Standby mode	430µA	ΟμΑ	550μΑ	1μA
POWERDOWN	Device Clock is off Relaxation Oscillator powered off PLL powered off Processor Core in STOP state All peripheral module and core clocks are off ADC powered off Voltage Regulator in Standby mode	300µA	ΟμΑ	400μΑ	1μΑ

Table 10-6 Current Consumption per Power Supply Pin (Typical)

1. No Output Switching All ports configured as inputs All inputs Low No DC Loads

Characteristic	Symbol	Min	Тур	Max	Unit
Low-Voltage Interrupt for 3.3V supply ¹	V _{EI3.3}	2.60	2.7		V
Low-Voltage Interrupt for 2.5V supply ²	V _{E12.5}	2.05	2.15	-	V
Low-Voltage Interrupt Recovery Hysteresis	V _{EIH}	_	50	_	mV
Power-On Reset ³	POR		1.8	1.9	V

 Table 10-7 Power-On Reset Low-Voltage Parameters

1. When V_{DD} drops below $V_{EI3.3}$, an interrupt is generated.

2. When V_{DD} drops below $V_{El32.5}$, an interrupt is generated.

3. Power-On Reset occurs whenever the internally regulated 2.5V digital supply drops below 1.8V. While power is ramping up, this signal remains active for as long as the internal 2.5V is below 2.15V or the 3.3V 1/O voltage is below 2.7V, no matter how long the ramp-up rate is. The internally regulated voltage is typically 100mV less than V_{DD} during ramp-up until 2.5V is reached, at which time it self-regulates.

10.2.1 Voltage Regulator Specifications

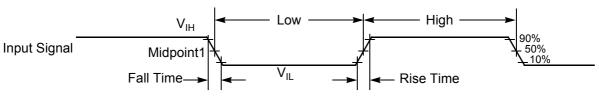
The 56F8014 has two on-chip regulators. One supplies the PLL and relaxation oscillator. It has no external pins and therefore has no external characteristics which must be guaranteed (other than proper operation of the device). The second regulator supplies approximately 2.5V to the 56F8014's core logic. This regulator requires an external 4.4μ F, or greater, capacitor for proper operation. Ceramic and tantalum capacitors tend to provide better performance tolerances. The output voltage can be measured directly on the V_{CAP} pin. The specifications for this regulator are shown in **Table 10-8**.

Characteristic	Symbol	Min	Typical	Max	Unit
Input Voltage	V _{IN}	3.0	_	3.6	V
Output Voltage	V _{OUT}	2.25	2.5	2.75	V
Short Circuit Current	I _{SS}	—	450	650	mA
Short Circuit Tolerance (output shorted to ground)	T _{RSC}	—	—	30	Minutes

Table 10-8. Regulator Parameters

10.3 AC Electrical Characteristics

Tests are conducted using the input levels specified in **Table 10-5**. Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured between the 10% and 90% points, as shown in **Figure 10-2**.



Note: The midpoint is V_{IL} + $(V_{IH} - V_{IL})/2$.

Figure 10-2 Input Signal Measurement References

Figure 10-3 shows the definitions of the following signal states:

- Active state, when a bus or signal is driven, and enters a low impedance state
- Tri-stated, when a bus or signal is placed in a high impedance state
- Data Valid state, when a signal level has reached $V_{OL} \mbox{ or } V_{OH}$
- Data Invalid state, when a signal level is in transition between V_{OL} and V_{OH}

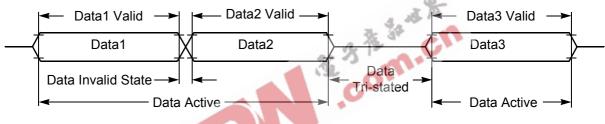


Figure 10-3 Signal States

10.4 Flash Memory Characteristics

Table 10-9 Flash Timing Parameters

Characteristic	Symbol	Min	Тур	Мах	Unit
Program time ¹	Tprog	20	_	40	μS
Erase time ²	Terase	20	—	_	ms
Mass erase time	Tme	100	—	_	ms

1. There is additional overhead which is part of the programming sequence. See the **56F801X Peripheral Reference Manual** for details.

2. Specifies page erase time. There are 512 bytes per page in the Program Flash memory.

10.5 External Clock Operation Timing

Characteristic	Symbol	Min	Тур	Мах	Unit
Frequency of operation (external clock driver) ²	f _{osc}	4	8	8	MHz
Clock Pulse Width ³	t _{PW}	6.25	—	—	ns
External Clock Input Rise Time ⁴	t _{rise}	—	—	3	ns
External Clock Input Fall Time ⁵	t _{fall}	—	—	3	ns

Table 10-10 External Clock Operation Timing Requirements¹

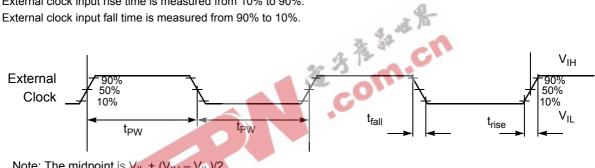
1. Parameters listed are guaranteed by design.

2. See Figure 10-4 for details on using the recommended connection of an external clock driver.

3. The high or low pulse width must be no smaller than 6.25ns or the chip may not function.

4. External clock input rise time is measured from 10% to 90%.

5. External clock input fall time is measured from 90% to 10%.



Note: The midpoint is $V_{IL} + (V_{IH} - V_{IL})/2$.

Figure 10-4 External Clock Timing

10.6 Phase Locked Loop Timing

Table 10-11 PLL Timing

Characteristic	Symbol	Min	Тур	Мах	Unit
Internal reference relaxation oscillator frequency for the PLL	f _{rosc}	_	8	_	MHz
PLL output frequency ¹ (24 x reference frequency)	f _{op}	_	192	_	MHz
PLL lock time ²	t _{lock}	_	40	100	μs
Cycle to cycle jitter	t _{jitterpll}		350		ps

1. The core system clock will operate at 1/6 of the PLL output frequency.

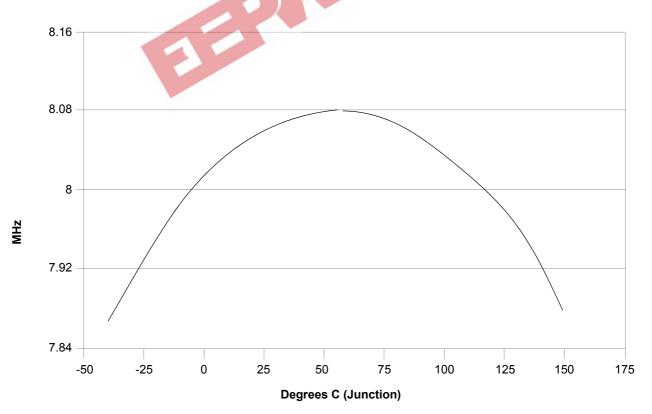
2. This is the time required after the PLL is enabled to ensure reliable operation.

10.7 Relaxation Oscillator Timing

Characteristic	Symbol	Minimum	Typical	Maximum	Unit
Relaxation Oscillator output frequency ¹ Normal Mode Standby Mode	f _{op}	_	8.05 200	_	MHz kHz
Relaxation Oscillator stabilization time ²	t _{roscs}	_	1	3	μs
Cycle-to-cycle jitter. This is measured on the CLKO signal (programmed prescaler_clock) over 264 clocks ³	t _{jitterrosc}	_	400		ps
Minimum tuning step size			.08		%
Maximum tuning step size			40		%
Variation over temperature -40°C to 150°C ⁴			+1.0 to -1.5	+3.0 to -3.0	%
Variation over temperature 0°C to 105°C ⁴		A.	0 to +1	+2.0 to -2.0	%
1. Output frequency after application of 8MHz trim	value, at 125°C	20 3			
2. This is the time required from standby to norma	Il mode transitio	n. 🕄 💦 🔨			
3. J _A is required to meet SCI requirements.		C			
4. See Figure 10-5.					

Table 10-12 Relaxation Oscillator Timing

- 3. J_A is required to meet SCI requirements.
- 4. See Figure 10-5.





10.8 Reset, Stop, Wait, Mode Select, and Interrupt Timing

Note: All the address and data buses described here are internal.

 Table 10-13 Reset, Stop, Wait, Mode Select, and Interrupt Timing^{1,2}

Characteristic	Symbol	Typical Min	Typical Max	Unit	See Figure
Minimum RESET Assertion Duration	t _{RA}	4T	_	ns	
Minimum GPIO pin Assertion for Interrupt	t _{IW}	2T	_	ns	10-6
RESET deassertion to First Address Fetch ³	t _{RDA}	96T _{OSC} + 64T	97T _{OSC} + 65T	ns	
Delay from Interrupt Assertion to Fetch of first instruction (exiting Stop)	t _{IF}	_	6T	ns	

1. In the formulas, T = clock cycle and T_{osc} = oscillator clock cycle. For an operating frequency of 32MHz, T = 31.25ns. At 8MHz (used during Reset and Stop modes), T = 125ns.

2. Parameters listed are guaranteed by design.

3. During Power-On Reset, it is possible to use the 56F8014 internal reset stretching circuitry to extend this period to 2²1T.

TIW

GPIO pin (Input)

Figure 10-6 GPIO Interrupt Timing (Negative Edge-Sensitive)

10.9 Serial Peripheral Interface (SPI) Timing

	1	1	I		
Characteristic	Symbol	Min	Max	Unit	See Figure
Cycle time Master Slave	t _C	125 62.5		ns ns	10-7, 10-8, 10-9, 10-10
Enable lead time Master Slave	t _{ELD}	 31		ns ns	10-10
Enable lag time Master Slave	t _{ELG}	 125		ns ns	10-10
Clock (SCK) high time Master Slave	t _{CH}	50 31	a In-	ns ns	10-7, 10-8, 10-9, 10-10
Clock (SCK) low time Master Slave	t _{CL}	50 31	I.C.	ns ns	10-10
Data set-up time required for inputs Master Slave	t _{DS}	20 0		ns ns	10-7, 10-8, 10-9, 10-10
Data hold time required for inputs Master Slave	t _{DH}	0 2	_	ns ns	10-7, 10-8, 10-9, 10-10
Access time (time to data active from high-impedance state) Slave	t _A	4.8	15	ns	10-10
Disable time (hold time to high-impedance state) Slave	t _D	3.7	15.2	ns	10-10
Data Valid for outputs Master Slave (after enable edge)	t _{DV}		4.5 20.4	ns ns	10-7, 10-8, 10-9, 10-10
Data invalid Master Slave	t _{DI}	0 0		ns ns	10-7, 10-8, 10-9, 10-10
Rise time Master Slave	t _R		11.5 10.0	ns ns	10-7, 10-8, 10-9, 10-10
Fall time Master Slave	t _F		9.7 9.0	ns ns	10-7, 10-8, 10-9, 10-10

Table 10-14 SPI Timing¹

1. Parameters listed are guaranteed by design.

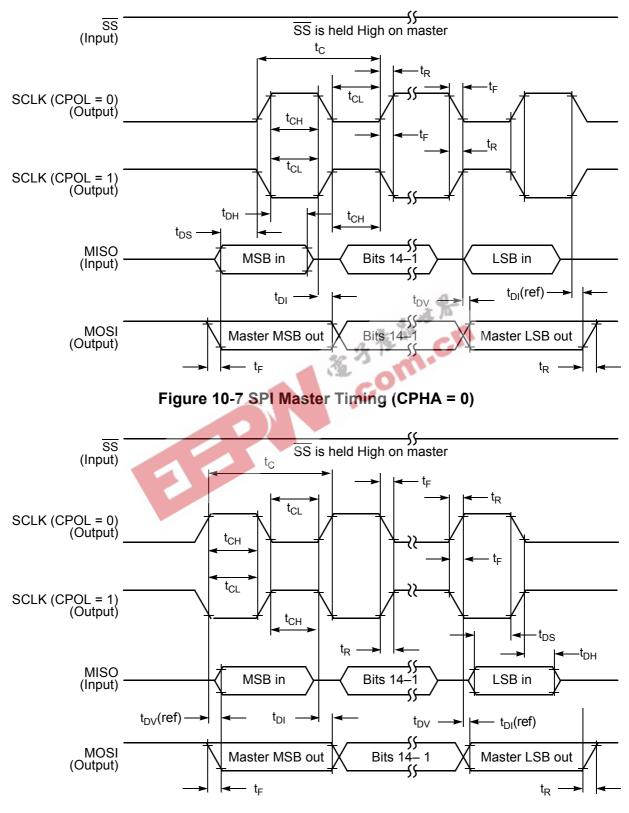


Figure 10-8 SPI Master Timing (CPHA = 1)

Serial Peripheral Interface (SPI) Timing

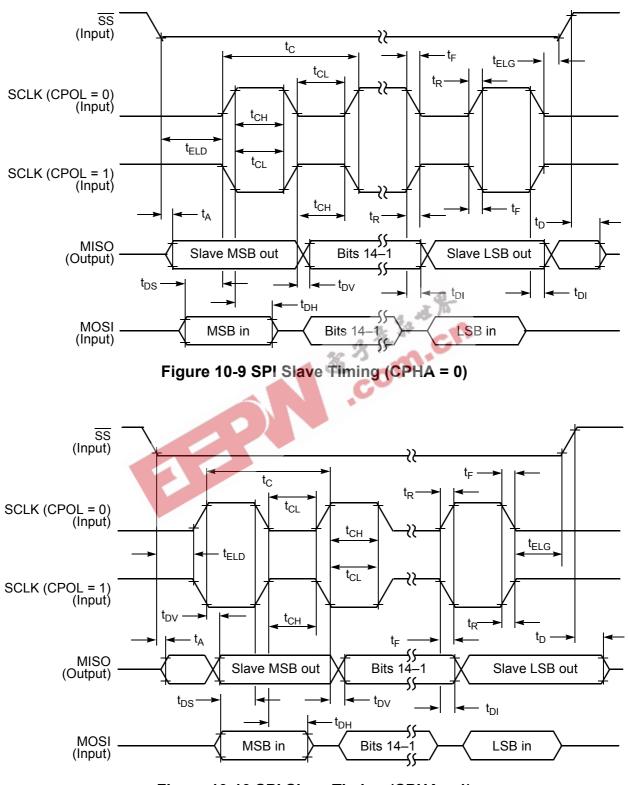


Figure 10-10 SPI Slave Timing (CPHA = 1)

10.10 Quad Timer Timing

Characteristic	Symbol	Min	Мах	Unit	See Figure
Timer input period	P _{IN}	2T + 6	_	ns	10-11
Timer input high / low period	P _{INHL}	1T + 3	_	ns	10-11
Timer output period	P _{OUT}	125	_	ns	10-11
Timer output high / low period	P _{OUTHL}	50	_	ns	10-11

Table 10-15 Timer Timing^{1, 2}

1. In the formulas listed, T = the clock cycle. For 32MHz operation, T = 31.25ns.

2. Parameters listed are guaranteed by design.

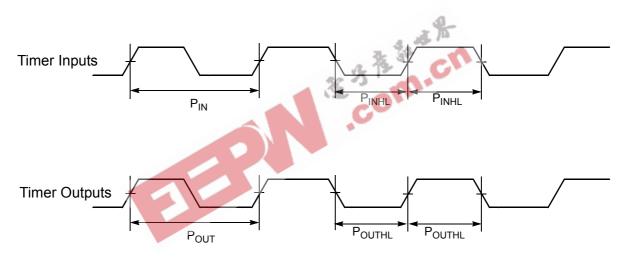


Figure 10-11 Timer Timing

10.11 Serial Communication Interface (SCI) Timing

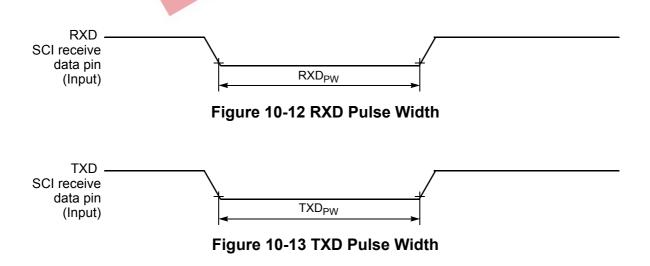
Characteristic	Symbol	Min	Мах	Unit	See Figure
Baud Rate ²	BR	—	(f _{MAX} /16)	Mbps	_
RXD ³ Pulse Width	RXD _{PW}	0.965/BR	1.04/BR	ns	10-12
TXD ⁴ Pulse Width	TXD _{PW}	0.965/BR	1.04/BR	ns	10-13
	LIN S	Slave Mode			
Deviation of slave node clock from nominal clock rate before synchronization	F _{TOL_UNSYN} CH	-14	14	%	
Deviation of slave node clock relative to the master node clock after synchronization	F _{TOL_SYNCH}	-2	2	%	
Minimum break character length	T _{BREAK}	133	M.Ch.	Master node bit periods	
		11		Slave node bit periods	

Table 10-16 SCI Timing¹

2. f_{MAX} is the frequency of operation of the system clock in MHz, which is 32MHz for the 56F8014 device.

3. The RXD pin in SCI0 is named RXD0 and the RXD pin in SCI1 is named RXD1.

4. The TXD pin in SCI0 is named TXD0 and the TXD pin in SCI1 is named TXD1.



10.12 Inter-Integrated Circuit Interface (I²C) Timing

Characteristic	Ourseland	Standa	rd Mode	Fast		
Gharacteristic	Symbol	Minimum	Maximum	Minimum	Maximum	Unit
SCL Clock Frequency	f _{SCL}	0	100	0	400	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	^t hd; sta	4.0		0.6		μS
LOW period of the SCL clock	t _{LOW}	4.7		1.25		μS
HIGH period of the SCL clock	t _{HIGH}	4.0		0.6		μS
Set-up time for a repeated START condition	t _{SU; STA}	4.7		0.6		μS
Data hold time for I ² C bus devices	t _{HD; DAT}	0 ¹	3.45 ²	1 0 ¹	0.9 ²	μS
Data set-up time	t _{SU; DAT}	250	2 7 5	100 ³		ns
Rise time of both SDA and SCL signals	t _r		1000	2 +0.1C _b ⁴	300	ns
Fall time of both SDA and SCL signals	t _f		\$ 300	2 +0.1C _b ⁴	300	ns
Set-up time for STOP condition	t _{SU; STO}	4.0		0.6		μS
Bus free time between STOP and START condition	t _{BUF}	4.7		1.3		μS
Pulse width of spikes that must be suppressed by the input filter	t _{SP}	N/A	N/A	0.0	50	ns

Table 10-17 I²C Timing

 A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the V_{IH} min of the SCL signal) to bridge the undefined region of the falling edge of SCL.

2. The maximum $t_{HD; DAT}$ has only to be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal.

3. A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement $t_{SU; DAT} > = 250$ ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line

 $t_{rmax} + t_{SU; DAT} = 1000 + 250 = 1250$ ns (according to the Standard mode I²C bus specification) before the SCL line is released. 4. C_b = total capacitance of the one bus line in pF.

JTAG Timing

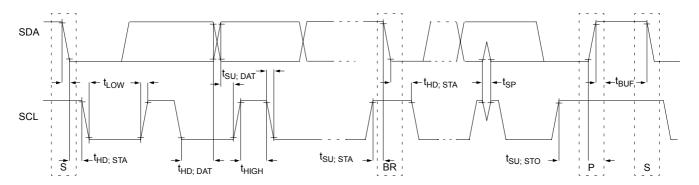


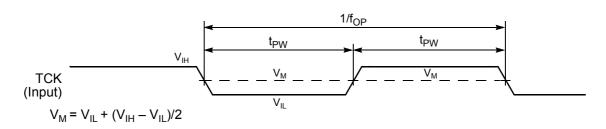
Figure 10-14 Timing Definition for Fast and Standard Mode Devices on the I²C Bus

10.13 JTAG Timing

Characteristic	Symbol	Min	Max	Unit	See Figure		
TCK frequency of operation ¹	f _{OP}	DC VS	SYS_CLK/8	MHz	10-15		
TCK clock pulse width	t _{PW}	50	-	ns	10-15		
TMS, TDI data set-up time	t _{DS}	5	—	ns	10-16		
TMS, TDI data hold time	t _{DH}	5	—	ns	10-16		
TCK low to TDO data valid	t _{DV}	—	30	ns	10-16		
TCK low to TDO tri-state	t _{TS}	—	30	ns	10-16		

Table 10-18 JTAG Timing

1. TCK frequency of operation must be less than 1/8 the processor rate.





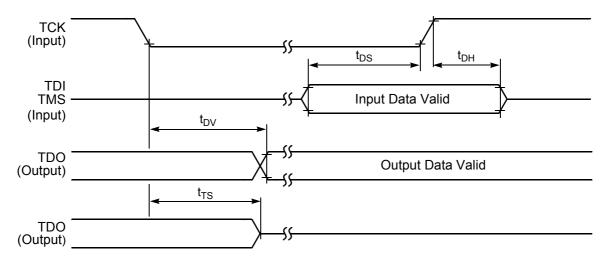


Figure 10-16 Test Access Port Timing Diagram



10.14 Analog-to-Digital Converter (ADC) Parameters

Parameter	Symbol	Min	Тур	Max	Unit
DC Specifications					
Resolution	R _{ES}	12	—	12	Bits
ADC internal clock	f _{ADIC}	0.1	—	5.33	MHz
Conversion range	R _{AD}	V _{REFL}	—	V _{REFH}	V
ADC power-up time ²	t _{ADPU}	—	6	13	t _{AIC} cycles ³
Recovery from auto standby	t _{REC}	—	0	1	t _{AIC} cycles ³
Conversion time	t _{ADC}		6	_	t _{AIC} cycles ³
Sample time	t _{ADS}	_	1		t _{AIC} cycles ³
Accuracy			0		
Integral non-linearity ⁴ (Full input signal range)	INL	_	+/- 3	+/- 5	LSB ⁵
Differential non-linearity	DNL		% 1* +/6	+/- 1	LSB ⁵
Monotonicity			GUARANTEED		
Offset Voltage Internal Ref	VOFFSET		+/- 4	+/- 9	mV
Offset Voltage External Ref	VOFFSET		+/- 6	+/- 12	mV
Gain Error (transfer gain)	E _{GAIN}	-	.998 to 1.002	1.01 to .99	_
ADC Inputs ⁶ (Pin Group 3)					
Input voltage (external reference)	V _{ADIN}	V _{REFL}	—	V _{REFH}	V
Input voltage (internal reference)	V _{ADIN}	V _{SSA}	—	V _{DDA}	V
Input leakage	I _{IA}	—	0	+/- 2	μA
V _{REFH} current	I _{VREFH}	—	0	—	μΑ
Input injection current ⁷ , per pin	I _{ADI}	—	—	3	mA
Input capacitance	C _{ADI}	_	See Figure 10-17	_	pF
Input impedance	X _{IN}	—	See Figure 10-17	_	Ohms
AC Specifications					
Signal-to-noise ratio	SNR	60	65		dB
Total Harmonic Distortion	THD	60	64		dB
Spurious Free Dynamic Range	SFDR	61	66		dB
Signal-to-noise plus distortion	SINAD	58	62		dB
Effective Number Of Bits	ENOB	_	10.0		Bits

Table 10-19 ADC Parameters¹

1. All measurements were made at V_{DD} = 3.3V, V_{REFH} = 3.3V, and V_{REFL} = ground

2. Includes power-up of ADC and $\,V_{\text{REF}}$

3. ADC clock cycles

- 4. INL measured from V_{IN} = V_{REFL} to V_{IN} = V_{REFH}
- 5. LSB = Least Significant Bit = 0.806mV

6. Pin groups are detailed following Table 10-1.

7. The current that can be injected or sourced from an unselected ADC signal input without impacting the performance of the ADC.

10.15 Equivalent Circuit for ADC Inputs

Figure 10-17 illustrates the ADC input circuit during sample and hold. S1 and S2 are always open/closed at the same time that S3 is closed/open. When S1/S2 are closed & S3 is open, one input of the sample and hold circuit moves to $(V_{REFH}-V_{REFL})/2$, while the other charges to the analog input voltage. When the switches are flipped, the charge on C1 and C2 are averaged via S3, with the result that a single-ended analog input is switched to a differential voltage centered about $(V_{REFH}-V_{REFL})/2$. The switches switch on every cycle of the ADC clock (open one-half ADC clock, closed one-half ADC clock). Note that there are additional capacitances associated with the analog input pad, routing, etc., but these do not filter into the S/H output voltage, as S1 provides isolation during the charge-sharing phase.

One aspect of this circuit is that there is an on-going input current, which is a function of the analog input voltage, V_{REF} and the ADC clock frequency.

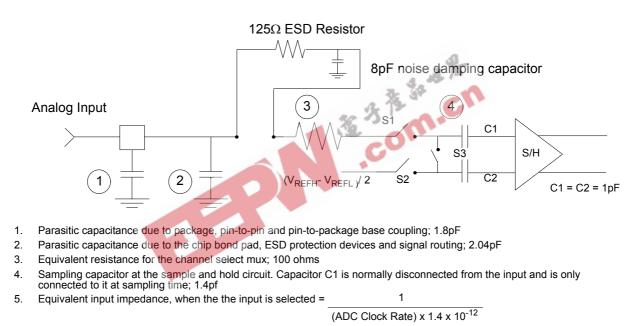


Figure 10-17 Equivalent Circuit for A/D Loading

10.16 Power Consumption

See Section 10.1 for a list of IDD requirements for the 56F8014. This section provides additional detail which can be used to optimize power consumption for a given application.

Power consumption is given by the following equation:

- Total power = A: internal [static component]
 - +B: internal [state-dependent component]
 - +C: internal [dynamic component]
 - +D: external [dynamic component]
 - +E: external [static]

A, the internal [static component], is comprised of the DC bias currents for the oscillator, leakage currents, PLL, and voltage references. These sources operate independently of processor state or operating frequency.

B, the internal [state-dependent component], reflects the supply current required by certain on-chip resources only when those resources are in use. These include RAM, Flash memory and the ADCs.

C, the internal [dynamic component], is classic C*V²*F CMOS power dissipation corresponding to the 56800E core and standard cell logic.

D, the external [dynamic component], reflects power dissipated on-chip as a result of capacitive loading on the external pins of the chip. This is also commonly described as $C*V^{2}*F$, although simulations on two of the I/O cell types used on the 56800E reveal that the power-versus-load curve does have a non-zero Y-intercept.

Table 10-20 I/O Loadi	ng Coefficients at 10MHz

	Intercept	Slope
8mA drive	1.3	0.11mW / pF
4mA drive	1.15mW	0.11mW / pF

Power due to capacitive loading on output pins is (first order) a function of the capacitive load and frequency at which the outputs change. **Table 10-20** provides coefficients for calculating power dissipated in the I/O cells as a function of capacitive load. In these cases:

 $TotalPower = \Sigma((Intercept + Slope*Cload)*frequency/10MHz)$

where:

- Summation is performed over all output pins with capacitive loads
- TotalPower is expressed in mW
- Cload is expressed in pF

Because of the low duty cycle on most device pins, power dissipation due to capacitive loads was found to be fairly low when averaged over a period of time.

E, the external [static component], reflects the effects of placing resistive loads on the outputs of the device. Sum the total of all V²/R or IV to arrive at the resistive load contribution to power. Assume V = 0.5 for the purposes of these rough calculations. For instance, if there is a total of eight PWM outputs driving 10mA into LEDs, then P = 8*.5*.01 = 40mW.

In previous discussions, power consumption due to parasitics associated with pure input pins is ignored, as it is assumed to be negligible.

Part 11 Packaging

11.1 56F8014 Package and Pin-Out Information

This section contains package and pin-out information for the 56F8014. This device comes in a 32-pin Low-profile Quad Flat Pack (LQFP). **Figure 11-1** shows the package outline for the 32-pin LQFP, **Figure 11-2** shows the mechanical parameters for this package, and **Table 11-1** lists the pin-out for the 32-pin LQFP.

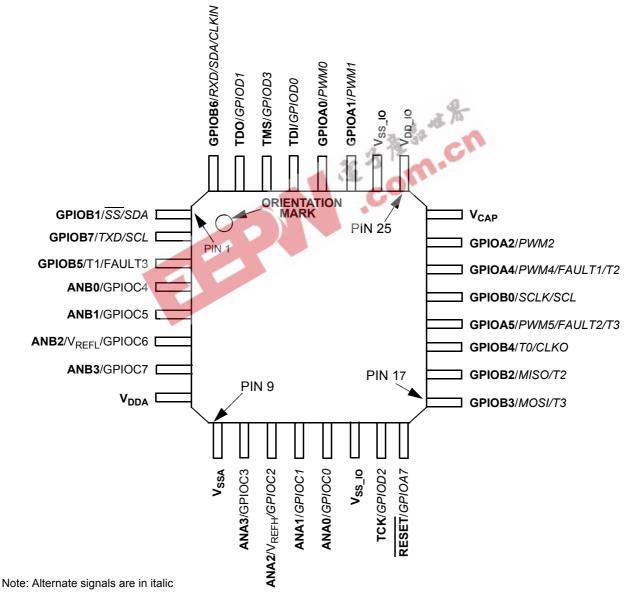


Figure 11-1 Top View, 56F8014 32-Pin LQFP Package

56F8014 Technical Data, Rev. 9

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
1	GPIOB1 SS,SDA	9	V _{SSA}	17	GPIOB3 MOSI,T3	25	V _{DD_IO}
2	GPIOB7 TXD,SCL	10	ANA3 GPIOC3	18	GPIOB2 MISO,T2	26	V _{SS_IO}
3	GPIOB5 <i>T1,FAULT3</i>	11	ANA2 V _{REFH} , GPIOC2	19	GPIOB4 T0,CLKO	27	GPIOA1 PWM1
4	ANB0 GPIOC4	12	ANA1 GPIOC1	20	GPIOA5 PWM5,FAULT2,T3	28	GPIOA0 PWM0
5	ANB1 GPIOC5	13	ANA0 GPIOC0	21	GPIOB0 SCLK/,CL	29	TDI GPIOD0
6	ANB2 V _{REFL} ,GPIOC6	14	V _{SS_IO}	22	GPIOA4 <i>PWM4/FAULT1/T2</i>	30	TMS GPIOD3
7	ANB3 GPIOC7	15	TCK GPIOD2	23	GPIOA2 PWM2	31	TDO GPIOD1
8	V _{DDA}	16	RESET GPIOA7	24	VCAP	32	GPIOB6 RXD,SDA,CLKIN
1.Alternat	e signals are in iltal	ic					

Table 11-1 56F8014 32-Pin LQFP Package Identification by Pin Number¹

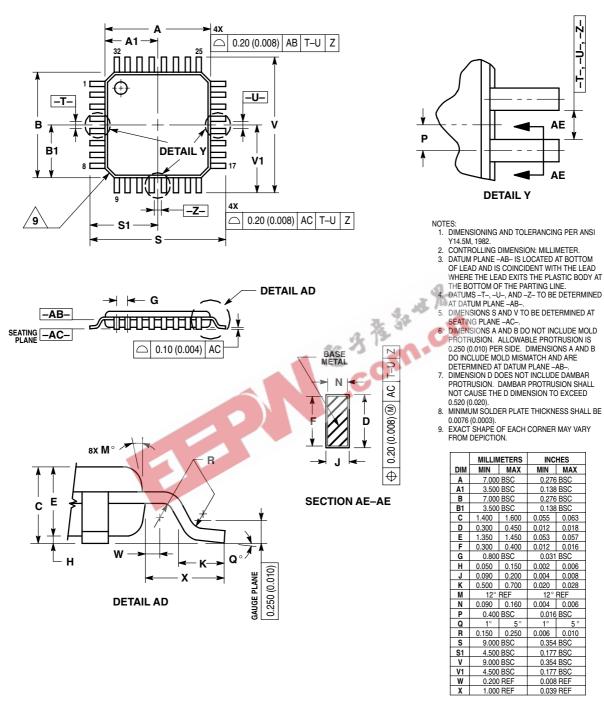


Figure 11-2 56F8014 32-Pin LQFP Mechanical Information

Please see http://www.freescale.com for the most current mechanical drawing.

Part 12 Design Considerations

12.1 Thermal Design Considerations

An estimation of the chip junction temperature, T_J, can be obtained from the equation:

 $T_{J} = T_{A} + (R_{\theta JA} \times P_{D})$

where:

 T_A = Ambient temperature for the package (°C)

 $R_{\theta JA}$ = Junction-to-ambient thermal resistance (°C/W)

 P_D = Power dissipation in the package (W)

The junction-to-ambient thermal resistance is an industry-standard value that provides a quick and easy estimation of thermal performance. Unfortunately, there are two values in common usage: the value determined on a single-layer board and the value obtained on a board with two planes. For packages such as the PBGA, these values can be different by a factor of two. Which value is closer to the application depends on the power dissipated by other components on the board. The value obtained on a single layer board is appropriate for the tightly packed printed circuit board. The value obtained on the board with the internal planes is usually appropriate if the board has low-power dissipation and the components are well separated.

When a heat sink is used, the thermal resistance is expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance:

 $R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$ where:

 $R_{\theta JA}$ = Package junction-to-ambient thermal resistance (°C/W) $R_{\theta JC}$ = Package junction-to-case thermal resistance (°C/W)

 $R_{\theta CA}$ = Package case-to-ambient thermal resistance (°C/W)

 $R_{\theta JC}$ is device related and cannot be influenced by the user. The user controls the thermal environment to change the case to ambient thermal resistance, $R_{\theta CA}$. For instance, the user can change the size of the heat sink, the air flow around the device, the interface material, the mounting arrangement on printed circuit board, or change the thermal dissipation on the printed circuit board surrounding the device.

To determine the junction temperature of the device in the application when heat sinks are not used, the Thermal Characterization Parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

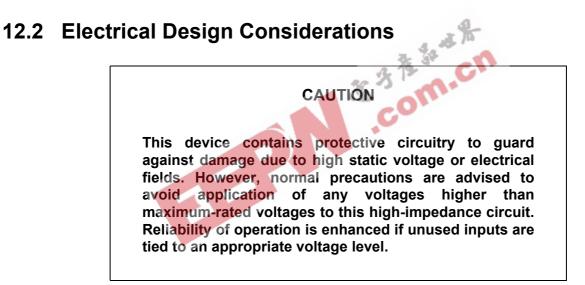
 $T_J = T_T + (\Psi_{JT} \times P_D)$ where:

 T_T = Thermocouple temperature on top of package (°C) Ψ_{JT} = Thermal characterization parameter (°C/W) P_D = Power dissipation in package (W)

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The thermal characterization parameter is measured per JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

When heat sink is used, the junction temperature is determined from a thermocouple inserted at the interface between the case of the package and the interface material. A clearance slot or hole is normally required in the heat sink. Minimizing the size of the clearance is important to minimize the change in thermal performance caused by removing part of the thermal interface to the heat sink. Because of the experimental difficulties with this technique, many engineers measure the heat sink temperature and then back-calculate the case temperature using a separate measurement of the thermal resistance of the interface. From this case temperature, the junction temperature is determined from the junction-to-case thermal resistance.



Use the following list of considerations to assure correct operation of the 56F8014:

- Provide a low-impedance path from the board power supply to each V_{DD} pin on the 56F8014 and from the board ground to each V_{SS} (GND) pin
- The minimum bypass requirement is to place 0.01–0.1µF capacitors positioned as close as possible to the package supply pins. The recommended bypass configuration is to place one bypass capacitor on each of the V_{DD}/V_{SS} pairs, including V_{DDA}/V_{SSA}. Ceramic and tantalum capacitors tend to provide better tolerances.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{DD} and V_{SS} (GND) pins are as short as possible
- Bypass the V_{DD} and V_{SS} with approximately 100 μ F, plus the number of 0.1 μ F ceramic capacitors
- PCB trace lengths should be minimal for high-frequency signals
- Consider all device loads as well as parasitic capacitance due to PCB traces when calculating capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{DD} and V_{SS} circuits.

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- Take special care to minimize noise levels on the V_{REF} , V_{DDA} and V_{SSA} pins
- Using separate power planes for V_{DD} and V_{DDA} and separate ground planes for V_{SS} and V_{SSA} is recommended. Connect the separate analog and digital power and ground planes as close as possible to power supply outputs. If both analog circuit and digital circuit are powered by the same power supply, it is advisable to connect a small inductor or ferrite bead in serial with both V_{DDA} and V_{SSA} traces.
- It is highly desirable to physically separate analog components from noisy digital components by ground planes. Do not place an analog trace in parallel with digital traces. It is also desirable to place an analog ground trace around an analog signal trace to isolate it from digital traces.
- Because the Flash memory is programmed through the JTAG/EOnCE port, SPI, SCI or I²C, the designer should provide an interface to this port if in-circuit Flash programming is desired.



Part 13 Ordering Information

Table 13-1 lists the pertinent information needed to place an order. Consult a Freescale Semiconductor sales office or authorized distributor to determine availability and to order parts.

Part	Supply Voltage	Package Type	Pin Count	Frequency (MHz)	Abient Temperature Range	Order Number
MC56F8014	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	32	32	-40° to + 105° C	MC56F8014VFAE*

Table 13-1 56F8014 Ordering Information

*This package is RoHS compliant.



Part 14 Appendix

Register acronyms are revised from previous device data sheets to provide a cleaner register description. A cross reference to legacy and revised acronyms are provided in the following table.

		Peripheral Re	ference Manual	Data	l Sheet	Processor	Memory Address	
Module	Register Name	New Acronym	Legacy Acronym	New Acronym	Legacy Acronym	Expert Acronym	Start	End
ADC	Control Register 1	CTRL1	ADCR1	ADC_CTRL1	ADC_ADCR1	ADC_ADCR1	0xF	080
	Control Register 2	CTRL2	ADCR2	ADC_CTRL2	ADC_ADCR2	 ADC_ADCR2	0xF	081
	Zero Crossing Control Register	ZXCTRL	ADZCC	ADC ZXCTRL	ADC ADZCC	ADC ADZCC	0xF082	
	Channel List Register 1	CLIST1	ADLST1	ADC CLIST1	ADC ADLST1	ADC ADLST1	0xF083	
	Channel List Register 2	CLIST2	ADLST2	ADC_CLIST2	ADC_ADLST2	ADC_ADLST2	0xF	084
	Sample Disable Register	SDIS	ADSDIS	ADC_SDIS	ADC ADSDIS	ADC ADSDIS	0xF	085
	Status Register	STAT	ADSTAT	 ADC_STAT	 ADC_ADSTAT	 ADC_ADSTAT	0xF	086
	Limit Status Register	LIMSTAT	ADLSTAT	ADC_LIMSTAT	ADC_ADLSTAT	ADC_ADLSTAT	0xF	087
	Zero Crossing Status Register	ZXSTAT	ADZCSTAT	ADC_ZXSTAT	ADC_ADZCSTAT	ADC_ADZCSTAT	0xF	088
	Result Registers 0-7	RSLT0-7	ADRSLT0-7	ADC_RSLT0-7	ADC_ADRSLT0-7	ADC_ADRSLT0-7	0xF089	0XF090
	Low Limit Registers 0-7	LOLIM0-7	ADLLMT0-7	ADC_LOLIM0-7	ADC_ADLLMT0-7	ADC_ADLLMT0-7	0XF091	0XF098
	High Limit Registers 0-7	HILIM0-7	ADHLMT0-7	ADC HILIMO-7	ADC ADHLMT0-7	ADC ADHLMT0-7	0XF099	0XF0A0
	Offset Registers 0-7	OFFST0-7	ADOFS0-7	ADC_OFFST0-7	ADC_ADOFS0-7	ADC_ADOFS0-7	0XF0A1	0XF0A8
	Power Control Register	PWR	ADPOWER	ADC_PWR	ADC_ADPOWER	 ADC_ADPOWER	0XF	0A9
	Voltage Reference Register	CAL	ADCAL	ADC VREF	ADC_ADCAL	ADC_CAL	0XF	0AA
		11 1		C		_		
COP	Control Register	CTRL	COPCTL	COP_CTRL	COPCTL	COPCTL	0XF	0E0
	Time-Out Register	TOUT	СОРТО	COP TOUT	СОРТО	COPTO	0XF0E1	
	Counter Register	CNTR	COPCTR	COP CNTR	COPCTR	COPCTR	0XF0E2	
		"		_				
I ² C	Address Register	ADDR	IBAD	I2C_ADDR	I2C_IBAD	IBAD	0xF0D0	
	Frequency Divider Register	FDIV	IBFD	I2C_FDIV	I2C_IBFD	IBFD	0xF	0D1
	Control Register	CTRL	IBCR	I2C_CTRL	I2C_IBCR	IBCR	0xF	0D2
	Status Register	STAT	IBSR	I2C_STAT	I2C_IBSR	IBSR	0xF	0D3
	Data I./O Register	DATA	IBDR	I2C_DATA	I2C_IBDR	IBDR	0xF	0D4
	Noise Filter Register	NFILT	IBNR	I2C_NFILT	I2C_IBNR	IBNR	0xF	0D5
				u.	1	l.		
ITCN	Interrupt Priority Register 0-4	N/A	N/A	ITCN_IPR0-4	ITCN_IPR0-4	INTC_IPR0-4	0XF060	0XF064
	Vector Base Address Register	N/A	N/A	ITCN_VBA	ITCN_VBA	INTC_VBA	0XF	065
	Fast Interrupt Match 0 Register	N/A	N/A	ITCN_FIM0	ITCN_FIM0	INTC_FIM0	0XF	066
	Fast Interrupt Vector Address Low 0	N/A	N/A	ITCN_FIVAL0	ITCN_FIVAL0	INTC_FIVAL0	0XF	067
	Fast Interrupt Vector Address High 0	N/A	N/A	ITCN_FIVAH0	ITCN_FIVAH0	INTC_FIVAH0	0XF068	
	Fast Interrupt Match 1 Register	N/A	N/A	ITCN_FIM1	ITCN_FIM1	INTC_FIM1	0xF069	
	Fast Interrupt Vector Address Low 1	N/A	N/A	ITCN_FIVAL1	ITCN_FIVAL1	INTC_FIVAL1	0xF	06A
	Fast Interrupt Vector Address High 1	N/A	N/A	ITCN_FIVAH1	ITCN_FIVAH1	INTC_FIVAH1	0xF	06B
	Interrupt Pending Register 0	N/A	N/A	ITCN_IRQP0	ITCN_IRQP0	INTC_IRQP0	0xF06C	
	Interrupt Pending Register 1	N/A	N/A	ITCN_IRQP1	ITCN_IRQP1	INTC_IRQP1	0xF	06D
	Interrupt Pending Register 2	N/A	N/A	ITCN_IRQP2	ITCN_IRQP2	INTC_IRQP2	0xF06E	
	Interrupt Control Register	N/A	N/A	ITCN_ICTRL	ITCN_ICTL	INTC_ICTL	0xF	072
occs	Control Register	CTRL	PLLCR	OCCS_CTRL	PLLCR	PLLCR	0xF	0F0
	Divide-By Register	DIVBY	PLLDB	OCCS_DIVBY	PLLDB	PLLDB	0xF	0F1
	Status Register	STAT	PLLSR	OCCS_STAT	PLLSR	PLLSR	0xF	0F2
	Shutdown Register	SHUTDN	SHUTDOWN	OCCS_SHUTDN	SHUTDOWN	SHUTDOWN	0xF	0F4
	Oscillator Control Register	OCTRL	OSCTL	OCCS OCTRL	OSCTL	OSCTL	0xF0F5	

		Peripheral Re	eference Manual	Data	a Sheet	Processor	Memory	Address
Module	Register Name	New Acronym	Legacy Acronym	New Acronym	Legacy Acronym	Expert Acronym	Start	End
FM	Clock Divider Register	CLKDIV	FMCLKD	FM CLKDIV	FMCLKD	FMCLKD	0xF	400
	Configuration Register	CNFG	FMCR	FM_CNFG	FMCR	FMCR		401
	Security High Half Register	SECHI	FMSECH	FM SECHI	FMSECH	FMSECH		403
	Security Low Half Register	SECLO	FMSECL	FM SECLO	FMSECL	FMSECL		404
	Protection Register	PROT	FMPROT	FM PROT	FMPROT	FMPROT		410
	User Status Register	USTAT	FMUSTAT	FM USTAT	FMUSTAT	FMUSTAT		413
	Command Register	CMD	FMCMD	FM CMD	FMCMD	FMCMD		414
	Address Register	ADDR	FMADDR	FM ADDR	FMADDR	-	0xF	416
	Data Buffer Register	DATA	FMDATA	FM DATA	FMDATA		0xF	418
	Optional Data 1 Register	OPT1	FMOPT1	FM OPT1	FMOPT1	FMOPT1	0xF	41B
	Test Array Signature Register	TSTSIG	FMTST_SIG	FM_TSTSIG	FMTST_SIG		0xF	
GPIO	Pull-Up Enable Register	PUPEN	PUR	GPIOx PUPEN	GPIOx PUR	x = A (n=0) B (n=1) GPIO x PUR	, ,	0 (n =3) 1 n 0
GPIU	Data Register	DATA	DR	GPIOX_PUPEN GPIOX DATA	GPIOX_POR GPIOX DR	GPIO_X_PUR GPIO X DR	0xF 0xF	
	Data Register			—	—	GPIO_X_DR GPIO x DDR		
	0	DDIR PEREN	DDR	GPIOx_DDIR	GPIOx_DDR		0xF	
	Peripheral Enable Register		PER	GPIOx_PEREN	GPIOx_PER	GPIO_x_PER	0xF	
	Interrupt Assert Register	IASSRT	IAR	GPIOx_IASSRT	GPIOx_IAR	GPIO_x_IAR		1 n 4
	Interrupt Enable Register	IEN	IENR IPOLR	GPIOx_IEN	GPIOx_IENR	GPIO_x_IENR		1 n 5
	Interrupt Edge Polarity Register	IEPOL	-	GPIOX_IEPOL	GPIOx_IPOLR	GPIO_x_IPOLR		1 n 6
	Interrupt Pending Register	IPEND	IPR	GPIOx_IPEND	GPIOx_IPR	GPIO_x_IPR	0xF1 n 7 0xF1 n 8	
	Interrupt Edge Sensitive Register	IEDGE	IESR	GPIOx_IEDGE	GPIOx_IESR	GPIO_x_IESR		
	Push-Pull Output Mode Control Register	PPOUTM	PPMODE	GPIOx_PPOUTM	GPIOx_PPMODE	GPIO_x_PPMODE		1 n 9
	Raw Data Register Drive Strength Control Register	RDATA DRIVE	RAWDATA DRIVE	GPIOX_RDATA GPIOX DRIVE	GPIOx_RAWDATA GPIOx DRIVE	GPIO_ x _RAWDATA GPIO_ x _DRIVE	0xF 0xF	1 n A 1 n B
	Birro Guorgan Gona or Rogiotor	DIAVE	Diave				UXI	
PS	Control Register	CTRL	LVICONTROL	PS_CTRL	LVICONTROL	LVICTRL	0xF	160
	Status Register	STAT	LVISTATUS	PS_STAT	LVISTATUS	LVISR	0xF	161
DIA/AA	Central Desister	OTOL	DMOTI				0	0.40
PWM	Control Register	CTRL	PMCTL	PWM_CTRL	PWM_PMCTL	PWM_PMCTL		040
	Fault Control Register	FCTRL	PMFCTL	PWM_FCTRL	PWM_PMFCTL	PWM_PMFCTL	0xF	
	Fault Status/Acknowledge Regis.	FLTACK	PMFSA	PWM_FLTACK	PWM_PMFSA	PWM_PMFSA		042
	Output Control Register	OUT	PMOUT	PWM_OUT	PWM_PMOUT	PWM_PMOUT		043
	Counter Register	CNTR	PMCNT	PWM_CNTR	PWM_PMCNT	PWM_PMCNT		044 045
	Counter Modulo Register	CMOD	MCM PMVAL0-5	PWM_CMOD	PWM_MCM	PWM_PWMCM	-	
	Value Register 0-5 Deadtime Register 0-1	VAL0-5 DTIM0-1	PMVAL0-5 PMDEADTM0-1	PWM_VAL0-5 PWM_DTIM0-1	PWM_PMVAL0-5 PWM_PMDEADTM 0-1	PWM_PWMVAL0-5 PWM_PMDEADTM0-	0xF046 0xF04C	
	Disable Mapping Register 1-2	DMAP1-2	PMDISMAP1-2	PWM_DMAP1-2	•	PWM_PMDISMAP1-2	0xF04E	0xF04F
	Configure Register	CNFG	PMCFG	PWM CNFG	PWM PMCFG	PWM PMCFG	0xF	050
	Channel Control Register	CCTRL	PMCCR	PWM CCTRL	PWM PMCCR	PWM PMCCR		051
	Port Register	PORT	PMPORT	PWM_PORT	PWM_PMPORT	PWM PMPORT		052
	Internal Correction Control Regis.	ICCTRL	PMICCR	PWM_ICCTRL	PWM_PMICCR	PWM_PMICCR		053
	Source Control Register	SCTRL	PMSRC	PWM_SCTRL	PWM_PMSRC	PWM_PMSRC		054
SCI	Baud Rate Register	RATE	SCIBR	SCI_RATE	SCI_SCIBR	SCI_SCIBR	٥vE	0B0
301	Control Register 1	CTRL1	SCIER	SCI_RATE SCI_CTRL1	SCI_SCIER	SCI_SCIER	0xF 0xF	
	Control Register 1	CTRL1 CTRL2	SCICR SCICR2	SCI_CTRL1	SCI_SCICR	SCI_SCICR SCI_SCICR2		0B1 0B2
	Status Register	STAT	SCICR2 SCISR	SCI_CTRL2	SCI_SCICR2	SCI_SCICR2 SCI_SCISR		0B2 0B3
	Data Register			SCI_STAT				
	Dala Reyislei	DATA	SCIDR	SULDATA	SCI_SCIDR	SCI_SCIDR	UXF	0B4

Electrical Design Considerations

Module		Peripheral Re	ference Manual	Data	a Sheet	Processor	Memory Address	
	Register Name	New Acronym	Legacy Acronym	New Acronym	Legacy Acronym	Expert Acronym	Start	End
					<u>, </u>			
SIM	Control Register	N/A	N/A	SIM_CTRL	SIM_CONTROL	SIM_CONTROL	0xF140	
	Reset Status Register	N/A	N/A	SIM_RSTAT	SIM_RSTSTS	SIM_RSTSTS	0xF141	
	Software Control Register 0-3	N/A	N/A	SIM_SWC0-3	SIM_SCR0-3	SIM_SCR0-3	0xF142	
	Most Significant Half JTAG ID	N/A	N/A	SIM_MSHID	SIM_MSH_ID	SIM_MSH_ID		146
	Least Significant Half JTAG ID	N/A	N/A	SIM_LSHID	SIM_LSH_ID	SIM_LSH_ID	-	147
	Power Control Register	N/A	N/A	SIM_PWR	SIM_POWER		0xF148	
	Clock Out Select Register	N/A	N/A	SIM_CLKOUT	SIM_CLKOSR	SIM_CLKOSR	0xF	
	GPIO Peripheral Select Register	N/A	N/A	SIM_GPS	SIM_GPS	SIM_GPS	0xF	
	Peripheral Clock Enable Register	N/A	N/A	SIM_PCE	SIM_PCE	SIM_PCE	0xF14C	
	I/O Short Address Location High	N/A	N/A	SIM_IOSAHI	SIM_ISALH	SIM_ISALH	0xF14D	
	I/O Short Address Location Low	N/A	N/A	SIM_IOSALO	SIM_ISALL	SIM_ISALL	0xF	14E
SPI	Status and Control Register	SCTRL	SPSCR	SPI_SCTRL	SPI_SPSCR	SPI_SCR	0xF0C0	
	Data Size and Control Register	DSCTRL	SPDSR	SPI_DSCTRL	SPI_SPDSR	SPI_DSR	0xF0C1	
	Data Receive Register	DRCV	SPDRR	SPI_DRCV	SPI_SPDRR	SPI_DRR	0xF	0C2
	Data Transmit Register	DXMIT	SPDTR	SPI_DXMIT	SPI_SPDTR	SPI_DTR		0C3
						n = 0,		
TMR	Compare Register 1	COMP1	TMRCMP1	TMRn_COMP1	TMRn_CMP1	TMR n_ CMP1	0xF	
	Compare Register 2	COMP2	TMRCMP2	TMRn_COMP2	TMRn_CMP2	TMR n_ CMP2	0xF	-
	Capture Register	CAPT	TMRCAP	TMRn_CAPT	TMR <i>n</i> _CAP	TMR n_ CAP	0xF	0 n 2
	Load Register	LOAD	TMRLOAD	TMRn_LOAD	TMRn_LOAD	TMR n_ LOAD	0xF	0 n 3
	Hold Register	HOLD	TMRHOLD	TMRn_HOLD	TMR n_ HOLD	TMR n_ HOLD	0xF	0 n 4
	Counter Register	CNTR	TMRCNTR	TMR n_CNTR	TMR <i>n</i> _CNTR	TMR n_ CNTR	0xF0 n 5	
	Control Register	CTRL	TMRCTRL	TMRn_CTRL	TMR <i>n</i> _CTRL	TMR n_ CTRL	0xF0 n 6	
	Status and Control Register	SCTRL	TMRSCR	TMRn_SCTRL	TMR n_ SCR	TMR n_ SCR	0xF	0 n 7
	Comparator Load Register 1	CMPLD1	TMRCMPLD1	TMRn_CMPLD1	TMR n_ CMPLD1	TMR n_ CMPLD1	0xF0 n 8	
	Comparator Load Register 2	CMPLD2	TMRCMPLD2	TMR n_ CMPLD2	TMR n_ CMPLD2	TMR n_ CMPLD2	0xF0 n 9	
	Comparator Status/Control Register	CSCTRL	TMRCOMSCR	TMRn_CSCTRL	TMRn_COMSCR	TMRn_COMSCR	0xF	0 n A



Electrical Design Considerations





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